

RX140 Group, RX110 Group

Differences Between the RX140 Group and the RX110 Group

Introduction

This application note is intended as a reference to points of difference between the peripheral functions, I/O registers, and pin functions of the RX140 Group and RX110 Group, as well as a guide to key points to consider when migrating between the two groups.

Unless specifically otherwise noted, the information in this application note applies to the 80-pin package version of the RX140 Group and the 64-pin package version of the RX110 Group as the maximum specifications. To confirm details of differences in the specifications of the electrical characteristics, usage notes, and setting procedures, refer to the User's Manual: Hardware of the products in question.

Target Devices

RX140 Group and RX110 Group

Contents

1.	Comparison of Built-In Functions of RX140 Group and RX110 Group	4
2.	Comparative Overview of Specifications	6
2.1	CPU	
2.2	Address Space	7
2.3	Resets	8
2.4	Option-Setting Memory	9
2.5	Voltage Detection Circuit	10
2.6	Clock Generation Circuit	13
2.7	Low Power Consumption	17
2.8	Register Write Protection Function	22
2.9	Exception Handling	23
2.10	Interrupt Controller	24
2.11	Buses	26
2.12	Data Transfer Controller	27
2.13	I/O Ports	29
2.14	Multi-Function Pin Controller	32
2.15	Multi-Function Timer Pulse Unit 2	49
2.16	Compare Match Timer	53
2.17	Realtime Clock	54
2.18	Serial Communications Interface	55
2.19	I ² C bus Interface	62
2.20	Serial Peripheral Interface	65
2.21	12-Bit A/D Converter	68
2.22	Temperature Sensor	75
2.23	Data Operation Circuit	76
2.24	RAM	77
2.25	Flash Memory	78
2.26	Packages	81
3.	Comparison of Pin Functions	92
3.1	64-Pin Package	
3.2	48-Pin Package	
0.2	40 F III F dokage	
4.	Important Information when Migrating Between MCUs	87
4.1	Notes on Functional Design	87
4.1.1	12-Bit AD Converter	87
4.1.2	Exception Vector Table	87
4.1.3	Restrictions on Comparison Function	87
4.1.4	Port Direction Register (PDR) Initialization	87
4.1.5	Scan Conversion Time of 12-Bit A/D Converter	88

1. Comparison of Built-In Functions of RX140 Group and RX110 Group

A comparison of the built-in functions of the RX140 Group and RX110 Group is provided below. For details of the functions, see section 2, Comparative Overview of Specifications and section 5, Reference Documents.

Table 1.1 is a comparison of built-in functions of RX140 Group and RX110 Group.

Table 1.1 Comparison of Built-In Functions of RX140 Group and RX110 Group

Function	RX110	RX140
<u>CPU</u>		
Operating modes		0
Address space		
Resets		
Option-setting memory (OFSM)		/
Voltage detection circuit (LVDAa): RX110, (LVDAb): RX140		
Clock generation circuit		
Clock frequency accuracy measurement circuit (CAC)		0
Low power consumption		
Register write protection function		<u> </u>
Exception handling		
Interrupt controller (ICUb)		
Buses		
Data transfer controller (DTCa): RX110, (DTCb): RX140		
Event link controller (ELC)	×	0
I/O ports		/
Multi-function pin controller (MPC)	_	/
Multi-function timer pulse unit 2 (MTU2b): RX110, (MTU2a): RX140		
Port output enable 2 (POE2a)	×	0
8-bit timer (TMRa)	X	0
Compare match timer (CMT)		
Realtime clock (RTCA): RX110, (RTCc): RX140		
Low-power timer (LPTa)	×	0
Independent watchdog timer (IWDTa)		0
Serial communications interface (SCIe, SCIf): RX110,		
(SClg*1, SClk, SClh): RX140		
<u>I²C bus interface (RIIC): RX110, (RIICa): RX140</u>		<u> </u>
CAN module (RSCAN0)	×	O *1
Serial peripheral interface (RSPI): RX110, (RSPIc): RX140		/_
CRC calculator (CRC)	1	0
Capacitive touch sensing unit (CTSU2SL, CTSU2L)	X	0
AESA	X	0
RNGA	X	0
12-bit A/D converter (S12ADb): RX110, (S12ADE): RX140		/
D/A converter (DAa)	X	0
Temperature sensor (TEMPSA)		
Comparator B (CMPBa)	X	0
Data operation circuit (DOC)		•
RAM		/
Flash memory (FLASH)		/
<u>Packages</u>		/

○: Available, X: Unavailable, •: Differs due to added functionality,

▲: Differs due to change in functionality, ■: Differs due to removed functionality.

Note: 1. Not implemented on products with ROM capacity of 64 KB.

2. Comparative Overview of Specifications

This section presents a comparative overview of specifications, including registers.

In the comparative overview, red text indicates functions which are included only in one of the MCU groups and also functions for which the specifications differ between the two groups.

In the register comparison, red text indicates differences in specifications for registers that are included in both groups and **black text** indicates registers which are included only in one of the MCU groups. Differences in register specifications are not listed.

2.1 CPU

Table 2.1 is a comparative overview of CPU, and Table 2.2 is a comparison of CPU registers.

Table 2.1 Comparative Overview of CPU

Item	RX110	RX140		
CPU	 Maximum operating frequency: 32 MHz 32-bit RX CPU Minimum instruction execution time: One instruction per clock cycle Address space: 4 GB, linear Register set of the CPU — General purpose: Sixteen 32-bit registers — Control: Eight 32-bit registers — Accumulator: One 64-bit register Basic instructions: 73 	 Maximum operating frequency: 48 MHz 32-bit RX CPU (RXv2) Minimum instruction execution time: One instruction per clock cycle Address space: 4 GB, linear Register set of the CPU — General purpose: Sixteen 32-bit registers — Control: Ten 32-bit registers — Accumulator: Two 72-bit registers Basic instructions: 75, variable-length instruction format Floating point instructions: 11 		
	 DSP instructions: 9 Addressing modes: 10 Data arrangement — Instructions: Little endian — Data: Selectable between little endian or big endian On-chip 32-bit multiplier: 32 × 32 → 64 bits On-chip divider: 32 / 32 → 32 bits Barrel shifter: 32 bits 	 DSP instructions: 23 Addressing modes: 11 Data arrangement — Instructions: Little endian — Data: Selectable between little endian or big endian On-chip 32-bit multiplier: 32 × 32 → 64 bits On-chip divider: 32 / 32 → 32 bits Barrel shifter: 32 bits 		
FPU		 Single-precision floating-point (32 bits) Data types and floating-point exceptions conform to IEEE 754 standard 		

Table 2.2 Comparison of CPU Registers

Register	Bit	RX110	RX140
EXTB		_	Exception table register
FPSW		_	Floating-point status word
ACC (RX110) ACC0, ACC1 (RX140)	_	Accumulator	Accumulator 0, accumulator 1

2.2 Address Space

Figure 2.1 is a comparative memory map of single-chip mode.

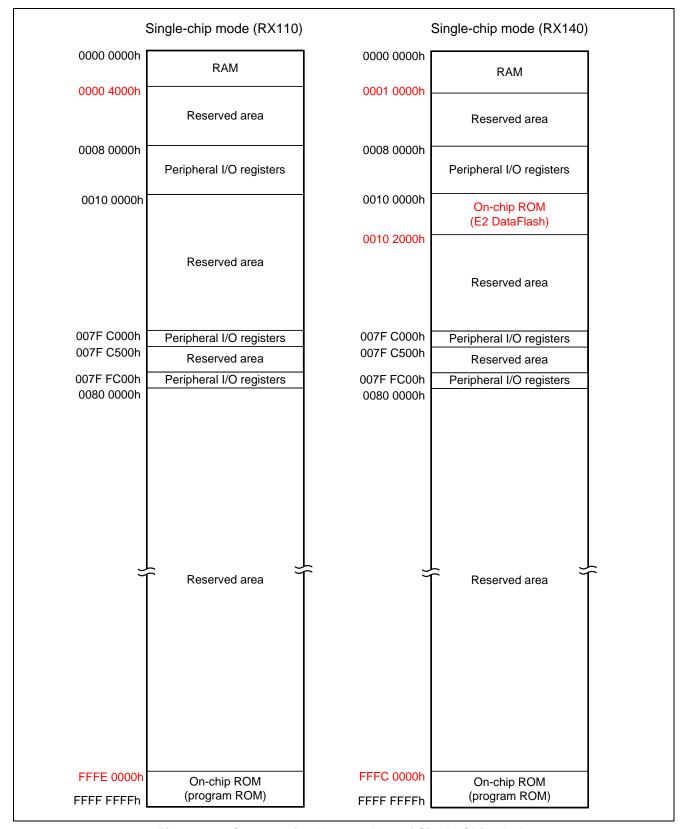


Figure 2.1 Comparative Memory Map of Single-Chip Mode

2.3 Resets

Table 2.3 is a comparative overview of resets, and Table 2.4 is a comparison of reset-related registers.

Table 2.3 Comparative Overview of Resets

Item	RX110	RX140
RES# pin reset	Voltage input to the RES# pin is	Voltage input to the RES# pin is
	driven low.	driven low.
Power-on reset	VCC rises	VCC rises
	(voltage detection: VPOR).	(voltage detection: VPOR).
Voltage monitoring 0 reset	_	VCC falls (voltage detection: Vdet0).
Voltage monitoring 1 reset	VCC falls (voltage detection: Vdet1).	VCC falls (voltage detection: Vdet1).
Voltage monitoring 2 reset	VCC falls (voltage detection: Vdet2).	VCC falls (voltage detection: Vdet2).
Independent watchdog	The independent watchdog timer	The independent watchdog timer
timer reset	underflows or a refresh error occurs.	underflows or a refresh error occurs.
Software reset	Register setting	Register setting

Table 2.4 Comparison of Reset-Related Registers

Register	Bit	RX110	RX140
RSTSR0	LVD0RF	_	Voltage monitor 0 reset detect flag

2.4 Option-Setting Memory

Table 2.5 is a comparison of option-setting memory registers.

Table 2.5 Comparison of Option-Setting Memory Registers

Register	Bit	RX110	RX140 (OFSM)
OFS1	FASTSTUP	Power-on fast startup time bit (b0)	Power-on fast startup time bit (b3)
	VDSEL[1:0]	_	Voltage detection 0 level select bits
	LVDAS	_	Voltage detection 0 circuit start bit
enable bits STUPLVD1LVL Startup voltage		Startup voltage monitoring 1 reset enable bits	_
		Startup voltage monitoring 1 reset detection level select bits	_
	HOCOFQ[1:0]	_	HOCO frequency selection bits

2.5 Voltage Detection Circuit

Table 2.6 is a comparative overview of the voltage detection circuits, and Table 2.7 is a comparison of voltage detection circuit registers.

Table 2.6 Comparative Overview of Voltage Detection Circuits

	RX110 (LVDAa)		RX140 (LVDAb)			
Item		Voltage Monitoring 1	Voltage Monitoring 2	Voltage Monitoring 0	Voltage Monitoring 1	Voltage Monitoring 2
VCC	Monitored	Vdet1	Vdet2	Vdet0	Vdet1	Vdet2
monitoring	Detection target	When voltage rises above or drops past Vdet1	When voltage rises above or drops past Vdet2 Switching between VCC and the voltage input on the CMPA2 pin can be accomplished using the LVCMPCR.EXV CCINP2 bit.	When voltage drops below Vdet0	When voltage rises above or drops past Vdet1	When voltage rises above or drops past Vdet2 Switching between VCC and the voltage input on the CMPA2 pin can be accomplished using the LVCMPCR.EXV CCINP2 bit.
	Detection voltage	Selectable from ten levels using LVDLVLR.LVD1 LVL[3:0] bits	Selectable from four levels using LVDLVLR.LVD2 LVL[1:0] bits	Selectable from four levels using the OFS1 register	Selectable from 14 levels using LVDLVLR.LVD1 LVL[3:0] bits	Selectable from four levels using LVDLVLR.LVD2 LVL[1:0] bits
	Monitoring flags	LVD1SR.LVD1M ON flag: Monitors whether voltage is higher or lower than Vdet1	LVD2SR.LVD2M ON flag: Monitors whether voltage is higher or lower than Vdet2	_	LVD1SR.LVD1M ON flag: Monitors whether voltage is higher or lower than Vdet1	LVD2SR.LVD2M ON flag: Monitors whether voltage is higher or lower than Vdet2
		LVD1SR.LVD1D ET flag: Vdet1 passage detection	LVD2SR.LVD2D ET flag: Vdet2 passage detection	_	LVD1SR.LVD1D ET flag: Vdet1 passage detection	LVD2SR.LVD2D ET flag: Vdet2 passage detection
Voltage detection processing	Reset	Voltage monitoring 1 interrupt	Voltage monitoring 2 interrupt	Voltage monitoring 0 interrupt	Voltage monitoring 1 interrupt	Voltage monitoring 2 interrupt
		Reset when Vdet1 > VCC: CPU restart timing selectable between after specified time with VCC > Vdet1 or Vdet1 > VCC	Reset when Vdet2 > VCC or CMPA2 pin: CPU restart timing selectable among after specified time with VCC or CMPA2 pin > Vdet2 or after specified time with Vdet2 > VCC or CMPA2 pin	Reset when Vdet0 > VCC: CPU restart timing after specified time with VCC > Vdet0	Reset when Vdet1 > VCC: CPU restart timing selectable between after specified time with VCC > Vdet1 or Vdet1 > VCC	Reset when Vdet2 > VCC or CMPA2 pin: CPU restart timing selectable among after specified time with VCC or CMPA2 pin > Vdet2 or after specified time with Vdet2 > VCC or CMPA2 pin

Item		RX110 (LVDAa)		RX140 (LVDAb)		
		Voltage Monitoring 1	Voltage Monitoring 2	Voltage Monitoring 0	Voltage Monitoring 1	Voltage Monitoring 2
Voltage detection processing	Interrupts	Voltage monitoring 1 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet1 > VCC, VCC > Vdet1, or both	Voltage monitoring 2 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet2 > VCC or CMPA2 pin, VCC or CMPA2 pin > Vdet2, or both		Voltage monitoring 1 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet1 > VCC, VCC > Vdet1, or both	Voltage monitoring 2 interrupt Selectable between non- maskable or maskable interrupt Interrupt request issued when Vdet2 > VCC, VCC > Vdet2, or both
Event link function		_	_	_	Available: Event output at Vdet passage detection	_

Table 2.7 Comparison of Voltage Detection Circuit Registers

Register	Bit	RX110 (LVDAa)	RX140 (LVDAb)
LVDLVLR	LVD1LVL[3:0]	Voltage detection 1 level select bits	Voltage detection 1 level select bits
		(Standard voltage during drop in	(Standard voltage during drop in
		voltage)	voltage)
		b3 b0	b3 b0
			0 0 0 0: 4.29 V
			0 0 0 1: 4.16 V
			0 0 1 0: 4.03 V
			0 0 1 1: 3.86 V
		0 1 0 0: 3.10 V	0 1 0 0: 3.10 V
		0 1 0 1: 3.00 V	0 1 0 1: 3.00 V
		0 1 1 0: 2.90 V	0 1 1 0: 2.90 V
		0 1 1 1: 2.79 V	0 1 1 1: 2.80 V
		1 0 0 0: 2.68 V	1 0 0 0: 2.68 V
		1 0 0 1: 2.58 V	1 0 0 1: 2.59 V
		1 0 1 0: 2.48 V	1 0 1 0: 2.48 V
		1 0 1 1: 2.06 V	1 0 1 1: 2.20 V
		1 1 0 0: 1.96 V	1 1 0 0: 1.96 V
		1 1 0 1: 1.86 V	1 1 0 1: 1.86 V
		Settings other than the above are	Settings other than the above are
		prohibited.	prohibited.
	LVD2LVL[1:0]	Voltage detection 2 level select bits	Voltage detection 2 level select bits
		(Standard voltage during drop in	(Standard voltage during drop in
		voltage)	voltage)
		b5 b4	b5 b4
		0 0: 2.90 V	0 0: 4.32 V
		0 1: 2.60 V	0 1: 4.17 V
		1 0: 2.00 V	1 0: 4.03 V
		1 1: 1.80 V*1	1 1: 3.84 V

Note: 1. When the value of the LVCMPCR.EXVCCINP2 bit is 0 (power supply voltage (VCC)), the setting value of 11b is prohibited.

2.6 Clock Generation Circuit

Table 2.8 is a comparative overview of the clock generation circuits, and Table 2.9 is a comparison of clock generation circuit registers.

Table 2.8 Comparative Overview of Clock Generation Circuits

Item	RX110	RX140
Uses	Generates the system clock (ICLK) to be supplied to the CPU, DTC, ROM, and RAM.	Generates the system clock (ICLK) to be supplied to the CPU, DTC, ROM, and RAM.
	 Of the peripheral module clocks (PCLKB and PCLKD) supplied to the peripheral modules, PCLKD is the operating clock for the S12AD, and PCLKB is the operating clock for modules other than S12AD. Generates the FlashIF clock (FCLK) to be supplied to the FlashIF. Generates the CAC clock (CACCLK) to be supplied to the CAC. 	 Of the peripheral module clocks (PCLKB and PCLKD) supplied to the peripheral modules, PCLKD is the operating clock for the S12AD, and PCLKB is the operating clock for modules other than S12AD. Generates the FlashIF clock (FCLK) to be supplied to the FlashIF. Generates the CAC clock (CACCLK) to be supplied to the CAC. Generates the CAN clock (CANMCLK) to be supplied to the CAN.
	Generates the RTC-dedicated sub- clock (RTCSCLK) to be supplied to the RTC.	Generates the RTC-dedicated sub- clock (RTCSCLK) to be supplied to the RTC.
	Generates the IWDT-dedicated clock (IWDTCLK) to be supplied to the IWDT.	Generates the IWDT-dedicated clock (IWDTCLK) to be supplied to the IWDT
		 Generates the LPT clock (LPTCLK) to be supplied to the LPT.
Operating frequency	 ICLK: 32 MHz (max.) PCLKB: 32 MHz (max.) PCLKD: 32 MHz (max.) FCLK: — 1 MHz to 32 MHz (for programming and erasing the ROM) 	 ICLK: 48 MHz (max.) PCLKB: 32 MHz (max.) PCLKD: 48 MHz (max.) FCLK: — 1 MHz to 48 MHz (for programming and erasing the ROM and E2 DataFlash)
		 48 MHz (max.) (for reading from the E2 DataFlash)
	CACCLK: Same as clock from respective oscillators	CACCLK: Same as clock from respective oscillators CANIMOLIE: 20 MHz (max)
	RTCSCLK: 32.768 kHzIWDTCLK: 15 kHz	 CANMCLK: 20 MHz (max.) RTCSCLK: 32.768 kHz IWDTCLK: 15 kHz LPTCLK: Same as clock from selected oscillator

Item	RX110	RX140
Main clock oscillator	 Resonator frequency: 1 MHz to 20 MHz (VCC ≥ 2.4 V), 1 MHz to 8 MHz (VCC < 2.4 V) External clock input frequency: 	Resonator frequency: 1 MHz to 20 MHz External clock input frequency:
	20 MHz (max.)	 External clock input frequency: 20 MHz (max.)
	Connectable resonator or additional circuit: ceramic resonator, crystal	 Connectable resonator or additional circuit: ceramic resonator, crystal
	Connection pins: EXTAL, XTALOscillation stop detection function:	Connection pins: EXTAL, XTALOscillation stop detection function:
	When a main clock oscillation stop is detected, the system clock source is switched to LOCO and MTU pin can be forcedly driven to high-impedance.	When a main clock oscillation stop is detected, the system clock source is switched to LOCO and MTU pin can be forcedly driven to high-impedance.
	Drive capacity switching function	Drive capacity switching function
Sub-clock	Resonator frequency: 32.768 kHz	Resonator frequency: 32.768 kHz
oscillator	Connectable resonator or additional circuit: crystal	 Connectable resonator or additional circuit: crystal
	Connection pins: XCIN and XCOUT	Connection pins: XCIN and XCOUT
DI I ' '		Drive capacity switching function
PLL circuit		Input clock source: Main clockInput pulse frequency division ratio:
		Selectable from 1, 2, and 4
		Input frequency: 4 MHz to 12 MHz
		 Frequency multiplication ratio: Selectable from 4 to 12 (increments of 0.5)
		 Oscillation frequency: 24 MHz to 48 MHz
High-speed on-chip oscillator (HOCO)	Oscillation frequency: 32 MHz	Oscillation frequency: 24 MHz, 32 MHz, 48 MHz
Low-speed on-chip oscillator (LOCO)	Oscillation frequency: 4 MHz	Oscillation frequency: 4 MHz
IWDT-dedicated on-chip oscillator	Oscillation frequency: 15 kHz	Oscillation frequency: 15 kHz

Table 2.9 Comparison of Clock Generation Circuit Registers

Register	Bit	RX110	RX140
SCKCR3	CKSEL[2:0]	Clock source select bits	Clock source select bits
		b10 b8	b10 b8
		0 0 0: LOCO	0 0 0: LOCO
		0 0 1: HOCO	0 0 1: HOCO
		0 1 0: Main clock oscillator	0 1 0: Main clock oscillator
		0 1 1: Sub-clock oscillator	0 1 1: Sub-clock oscillator
			1 0 0: PLL circuit
		Settings other than the above are	Settings other than the above are
		prohibited.	prohibited.
PLLCR		_	PLL control register
PLLCR2		_	PLL control register 2

Register	Bit	RX110	RX140
SOSCCR	SOSTP	Sub-clock oscillator stop bit	Sub-clock oscillator stop bit
			This bit is not initialized by reset sources other than a power-on reset.
		Initial value after a reset differs.	
OSCOVFSR	PLOVF	_	PLL clock oscillation stabilization flag b2 0: PLL is stopped or not stabilized. 1: Oscillation is stable and the
			clock can be used as the system clock.
MOSCWTCR	MSTS[4:0]	Main clock oscillator wait time bits	Main clock oscillator wait time bits
		b4 b0 0 0 0 0 0: Wait time = 2 cycles (0.5 μs) 0 0 0 0 1: Wait time = 1,024 cycles (256 μs) 0 0 0 1 0: Wait time = 2,048 cycles (512 μs) 0 0 0 1 1: Wait time = 4,096 cycles (1.024 ms) 0 0 1 0 0: Wait time = 8,192 cycles (2.048 ms) 0 0 1 0 1: Wait time = 16,384 cycles (4.096 ms) 0 0 1 1 0: Wait time = 32,768 cycles (8.192 ms) 0 0 1 1 1: Wait time = 65,536 cycles (16.384 ms)	b4 b0 0 0 0 0 0: Wait time = 0 cycles (0 μs) 0 0 0 0 1: Wait time = 1,024 cycles (256 μs) 0 0 0 1 0: Wait time = 2,048 cycles (512 μs) 0 0 0 1 1: Wait time = 4,096 cycles (1.024 ms) 0 0 1 0 0: Wait time = 8,192 cycles (2.048 ms) 0 0 1 0 1: Wait time = 16,384 cycles (4.096 ms) 0 0 1 1 0: Wait time = 32,768 cycles (8.192 ms) 0 0 1 1 1: Wait time = 65,536 cycles (16.384 ms) 0 1 0 0 0: Wait time = 131,072 cycles (32.768 ms)
		Settings other than the above are prohibited. Wait time when LOCO = 4.0 MHz	Settings other than the above are prohibited. Wait time when LOCO = 4.0 MHz
		(0.25 µs, typ.)	(0.25 µs, typ.)
LOFCR	_	_	Low-speed on-chip oscillator forced oscillation control register
HOCOWTCR	_	High-speed on-chip oscillator wait control register	

CKOCR CKOSEL[2:0] (RX110) CLKOUT output source select bits (RX110) CKOSEL[3:0] (RX140) b10 b8 0 0 0 : LOCO clock 0 0 1 : HOCO clock 0 0 10 : HOCO clock 0 10 : Main clock oscillator 0 11 : Sub-clock oscillator 0 10 : Main clock oscillator 0 : Main clock oscillator drive capability switch bit MOFCR MODRV21 Main clock oscillator drive capability switch bit 0 : MHz to 10 MHz 1: 10 MHz to 20 MHz Main clock oscillator drive capability switch bit 0 : MHz to 20 MHz Main clock oscillator drive capability switch bit 0 : MHz to 20 MHz C: 1 MHz to 20 MHz 1: 10 MHz to 20 MHz C: 1 MHz to 20 MHz Co: 1 MHz to 20 MHz	Register	Bit	RX110	RX140
CKOSEL[3:0] (RX140)	CKOCR		CLKOUT output source select bits	CLKOUT output source select bits
RX140		, ,		
0 1 0: Main clock oscillator 0 1 1: Sub-clock oscillator 0 1 1: Sub-clock oscillator 0 1 1 : Sub-clock oscillator 0 1 1 : Sub-clock oscillator 0 1 1 : Sub-clock oscillator 0 1 1 0 0: PLL 1 0 0 0: CTSU internal clock Settings other than the above are prohibited. CKOCR		(RX140)		
Description				
Settings other than the above are prohibited. 10 00: CTSU internal clock Settings other than the above are prohibited. CKOCR				
Settings other than the above are prohibited. CLKOUT output division ratio select bits			0 1 1: Sub-clock oscillator	
CKOCR CKODIV[2:0] CLKOUT output division ratio select bits CLKOUT output division ratio select bits b14 b12 b14 b12 b14 b12 0 0 0: No division 0 0 0: No division 0 0 0: No division 0 1 : x1/2 0 1 0: x1/4 0 1 0: x1/4 0 1 1: x1/8 0 1 1: x1/8 1 1 0: x1/46 1 0 0: x1/16 1 0 0: x1/16 1 0 0: x1/16 Settings other than the above are prohibited. 1 1 0: x1/32 1 1 0: x1/32 MOFCR MODRV21 Main clock oscillator drive capability switch bit Main clock oscillator drive capability switch bit VCC ≥ 2.4 V 0: 1 MHz to 10 MHz 0: 1 MHz to less than 10 MHz 1: 10 MHz to 20 MHz 1: 10 MHz to 20 MHz LOCOTRR2 — — LOCOTRR — Low-speed on-chip oscillator trimming register 2 ILOCOTRR — — IWDT-dedicated on-chip oscillator trimming register n (n = 0) SOMCR — — Sub-clock oscillator mode control			Cotting as a through a share and	
CKOCR				
Select bits Select bits				prohibited.
b14 b12	CKOCR	CKODIV[2:0]	•	
0 0 0 : No division 0 0 0 : No division 0 0 1: ×1/2 0 1 0: ×1/4 0 1 0: ×1/4 0 1 1: ×1/8 1 0 0: ×1/16 Settings other than the above are prohibited. 1 0 1: ×1/32 11 0: ×1/64 11 1: ×1/128 MOFCR			select bits	select bits
0 0 1: ×1/2			b14 b12	b14 b12
0 1 0: ×1/4 0 1 1: ×1/8 0 1 0: ×1/4 0 1 1: ×1/8 1 0 0: ×1/16 Settings other than the above are prohibited. 1 0 1: ×1/32 1 1 0: ×1/64 1 1 1: ×1/128 MOFCR MODRV21 Main clock oscillator drive capability switch bit VCC ≥ 2.4 V 0: 1 MHz to 10 MHz 1: 10 MHz to 20 MHz 1: 10 MHz to 20 MHz 1: 10 MHz to 20 MHz LOCOTRR2 — Low-speed on-chip oscillator trimming register 2 IMDT-dedicated on-chip oscillator trimming register HOCOTRRn — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control Sub-clock oscillator mode control Indicator Indicator mode control Indicator mode control Indicator mod			0 0 0: No division	0 0 0: No division
D 1 1: ×1/8			0 0 1: ×1/2	0 0 1: ×1/2
1 0 0: ×1/16 1 0 0: ×1/16 1 0 0: ×1/16 Settings other than the above are prohibited.			0 1 0: ×1/4	0 1 0: ×1/4
Settings other than the above are prohibited. Settings other than the above are prohibited. 1 0 1: ×1/32 1 1 0: ×1/64 1 1 1: ×1/128			0 1 1: ×1/8	0 1 1: ×1/8
MOFCR MODRV21 Main clock oscillator drive capability switch bit Main clock oscillator drive capability switch bit VCC ≥ 2.4 V 0: 1 MHz to 10 MHz 1: 10 MHz to 20 MHz 0: 1 MHz to less than 10 MHz 1: 10 MHz to 20 MHz VCC < 2.4 V 0: 1 MHz to 8 MHz 1: Setting prohibited 1: 10 MHz to 20 MHz LOCOTRR2 — Low-speed on-chip oscillator trimming register 2 ILOCOTRR — IWDT-dedicated on-chip oscillator trimming register HOCOTRRn — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control			1 0 0: ×1/16	1 0 0: ×1/16
MOFCR MODRV21 Main clock oscillator drive capability switch bit VCC ≥ 2.4 V 0: 1 MHz to 10 MHz 1: 10 MHz to 20 MHz VCC < 2.4 V 0: 1 MHz to 8 MHz 1: Setting prohibited LOCOTRR2 LOCOTRR2 LOCOTRR Main clock oscillator drive capability switch bit O: 1 MHz to less than 10 MHz 1: 10 MHz to 20 MHz Low-speed on-chip oscillator trimming register 2 ILOCOTRR WDT-dedicated on-chip oscillator trimming register HOCOTRR High-speed on-chip oscillator trimming register n (n = 0) SOMCR Sub-clock oscillator mode control			Settings other than the above are	1 0 1: ×1/32
MOFCR MODRV21 Main clock oscillator drive capability switch bit Main clock oscillator drive capability switch bit VCC ≥ 2.4 V			prohibited.	1 1 0: ×1/64
Capability switch bit capability switch bit VCC ≥ 2.4 V 0: 1 MHz to 10 MHz 1: 10 MHz to 20 MHz 0: 1 MHz to less than 10 MHz 1: 10 MHz to 20 MHz VCC < 2.4 V 0: 1 MHz to 8 MHz 1: Setting prohibited Low-speed on-chip oscillator trimming register 2 LOCOTRR2 — IWDT-dedicated on-chip oscillator trimming register HOCOTRRn — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control				
VCC ≥ 2.4 V 0: 1 MHz to 10 MHz 0: 1 MHz to less than 10 MHz 1: 10 MHz to 20 MHz 1: 10 MHz to 20 MHz VCC < 2.4 V	MOFCR	MODRV21		
0: 1 MHz to 10 MHz 1: 10 MHz to 20 MHz 1: 10 MHz to 20 MHz			capability switch bit	capability switch bit
0: 1 MHz to 10 MHz 1: 10 MHz to 20 MHz 1: 10 MHz to 20 MHz			VCC > 2.4 V	
1: 10 MHz to 20 MHz VCC < 2.4 V 0: 1 MHz to 8 MHz 1: Setting prohibited LOCOTRR2 Low-speed on-chip oscillator trimming register 2 ILOCOTRR IL				0: 1 MHz to less than 10 MHz
VCC < 2.4 V				
DCOTRR2 LOCOTRR2 LOCOTRR2 Low-speed on-chip oscillator trimming register 2 ILOCOTRR IWDT-dedicated on-chip oscillator trimming register HOCOTRR High-speed on-chip oscillator trimming register n (n = 0) SOMCR Sub-clock oscillator mode control				
LOCOTRR2 — Low-speed on-chip oscillator trimming register 2 ILOCOTRR — IWDT-dedicated on-chip oscillator trimming register HOCOTRR — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control			VCC < 2.4 V	
LOCOTRR2 — Low-speed on-chip oscillator trimming register 2 ILOCOTRR — IWDT-dedicated on-chip oscillator trimming register HOCOTRRN — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control			0: 1 MHz to 8 MHz	
ILOCOTRR — IWDT-dedicated on-chip oscillator trimming register HOCOTRRN — — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — — Sub-clock oscillator mode control			1: Setting prohibited	
ILOCOTRR — IWDT-dedicated on-chip oscillator trimming register HOCOTRRN — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control	LOCOTRR2	-	_	
HOCOTRRN — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control	U 0007D5			5 5
HOCOTRRN — High-speed on-chip oscillator trimming register n (n = 0) SOMCR — Sub-clock oscillator mode control	ILOCOTRR		_	l ·
SOMCR — trimming register n (n = 0) Sub-clock oscillator mode control	HOCOTODs			5 5
SOMCR — Sub-clock oscillator mode control	INCOTRRIT		_	
	SOMCR	<u> </u>		
				register

2.7 Low Power Consumption

Table 2.10 is a comparative overview of the low power consumption functions, Table 2.11 is a comparison of procedures for entering and exiting low power consumption modes and operating states in each mode, and Table 2.12 is a comparison of low power consumption registers.

Table 2.10 Comparative Overview of Low Power Consumption Functions

Item	RX110	RX140	
Reducing power consumption by switching clock signals	The frequency division ratio can be set independently for the system clock (ICLK), peripheral module clock (PCLKB), S12AD clock (PCLKD), and FlashIF clock (FCLK).	The frequency division ratio can be set independently for the system clock (ICLK), peripheral module clock (PCLKB), S12AD clock (PCLKD), and FlashIF clock (FCLK).	
Module stop function	Each peripheral module can be stopped independently by the module stop control register.	Each peripheral module can be stopped independently by the module stop control register.	
Function for transition to low power consumption mode	Transition to a low power consumption mode in which the CPU, peripheral modules, or oscillators are stopped is enabled.	Transition to a low power consumption mode in which the CPU, peripheral modules, or oscillators are stopped is enabled.	
Low power consumption modes	Sleep modeDeep sleep modeSoftware standby mode	Sleep modeDeep sleep modeSoftware standby modeSnooze mode	
Function for lower operating power consumption	Power consumption can be reduced in normal operation, sleep mode, and deep sleep mode by selecting an appropriate operating power control mode according to the operating frequency and operating voltage. These appreciate power control mode.	Power consumption can be reduced in normal operation, sleep mode, deep sleep mode, and snooze mode by selecting an appropriate operating power control mode according to the operating frequency and operating voltage. Town a partial request. Town a partial reader. Town a partial reader.	
	 Three operating power control modes are available High-speed operating mode Middle-speed operating mode Low-speed operating mode 	 Four operating power control modes are available High-speed operating mode Middle-speed operating mode Middle-speed operating mode 2 Low-speed operating mode 	

Table 2.11 Comparison of Procedures for Entering and Exiting Low Power Consumption Modes and Operating States in Each Mode

<u> </u>	Entering and Exiting Low Power		
	Consumption Modes and		
Mode	Operating States	RX110	RX140
Sleep mode	Transition method	Control register	Control register
		+ instruction	+ instruction
	Method of cancellation other than reset	Interrupt	Interrupt
	State after cancellation	Program execution	Program execution
		state (interrupt	state (interrupt
		processing)	processing)
	Main clock oscillator	Operation possible	Operation possible
	Sub-clock oscillator	Operation possible	Operation possible
	High-speed on-chip oscillator	Operation possible	Operation possible
	Low-speed on-chip oscillator	Operation possible	Operation possible
	IWDT-dedicated on-chip oscillator	Operation possible	Operation possible
	PLL	_	Operation possible
	CPU	Stopped (retained)	Stopped (retained)
	RAMO	Operation possible	Operation possible
	(0000 0000h to 0000 3FFFh: RX110, 0000 0000h to 0000 FFFFh: RX140)	(retained)	(retained)
	DTC	Operation possible	Operation possible
	Flash memory	Operation	Operation
	Independent watchdog timer (IWDT)	Operation possible	Operation possible
	Realtime clock (RTC)	Operation possible	Operation possible
	Low-power timer (LPT)	_	Operation possible
	Voltage detection circuit (LVD)	Operation possible	Operation possible
	Power-on reset circuit	Operation	Operation
	Peripheral modules	Operation possible	Operation possible
	I/O ports	Operation	Operation
	RTCOUT output	Operation possible	Operation possible
	CLKOUT output	Operation possible	Operation possible
	Comparator B	_	Operation possible
Deep sleep	Transition method	Control register	Control register
mode	Mathead of consultation of an theory and	+ instruction	+ instruction
	Method of cancellation other than reset	Interrupt	Interrupt
	State after cancellation	Program execution state (interrupt	Program execution state (interrupt
		processing)	processing)
	Main clock oscillator	Operation possible	Operation possible
	Sub-clock oscillator	Operation possible	Operation possible
	High-speed on-chip oscillator	Operation possible	Operation possible
	Low-speed on-chip oscillator	Operation possible	Operation possible
	IWDT-dedicated on-chip oscillator	Operation possible	Operation possible
	PLL	_	Operation possible
	CPU	Stopped (retained)	Stopped (retained)
	RAM0	Stopped (retained)	Stopped (retained)
	(0000 0000h to 0000 3FFFh: RX110,		
	0000 0000h to 0000 FFFFh: RX140)		
	DTC	Stopped (retained)	Stopped (retained)
	Flash memory	Stopped (retained)	Stopped (retained)
	Independent watchdog timer (IWDT)	Operation possible	Operation possible
	Realtime clock (RTC)	Operation possible	Operation possible

	Entering and Exiting Low Power Consumption Modes and		
Mode	Operating States	RX110	RX140
Deep sleep	Low-power timer (LPT)		Operation possible
mode	Voltage detection circuit (LVD)	Operation possible	Operation possible
	Power-on reset circuit	Operation	Operation
	Peripheral modules	Operation possible	Operation possible
	I/O ports	Operation	Operation
	RTCOUT output	Operation possible	Operation possible
	CLKOUT output	Operation possible	Operation possible
	Comparator B		Operation possible
Software standby mode	Transition method	Control register + instruction	Control register + instruction
	Method of cancellation other than reset	Interrupt	Interrupt
	State after cancellation	Program execution state (interrupt processing)	Program execution state (interrupt processing)
	Main clock oscillator	Stopped	Stopped
	Sub-clock oscillator	Operation possible	Operation possible
	High-speed on-chip oscillator	Stopped	Operation possible
	Low-speed on-chip oscillator	Stopped	Operation possible
	IWDT-dedicated on-chip oscillator	Operation possible	Operation possible
	PLL	_	Stopped
	CPU	Stopped (retained)	Stopped (retained)
	RAM0 (0000 0000h to 0000 3FFFh: RX110, 0000 0000h to 0000 FFFFh: RX140)	Stopped (retained)	Stopped (retained)
	DTC	Stopped (retained)	Stopped (retained)
	Flash memory	Stopped (retained)	Stopped (retained)
	Independent watchdog timer (IWDT)	Operation possible	Operation possible
	Realtime clock (RTC)	Operation possible	Operation possible
	Low-power timer (LPT)	_	Operation possible
	Voltage detection circuit (LVD)	Operation possible	Operation possible
	Power-on reset circuit	Operation	Operation
	Peripheral modules	Stopped (retained)	Stopped (retained)
	I/O ports	Retained	Retained
	RTCOUT output	Operation possible	Operation possible
	CLKOUT output	Operation possible	Operation possible
	Comparator B		Operation possible
Snooze mode	Transition method		Occurrence of snooze request condition while in software standby mode
	Method of cancellation other than reset	_	Interrupt or occurrence of snooze end condition
	State after cancellation	_	Program execution state (interrupt processing) or software standby mode
	Main clock oscillator	_	Operation possible

	Entering and Exiting Low Power		
Mode	Consumption Modes and Operating States	RX110	RX140
Snooze mode	Sub-clock oscillator	_	Operation possible
	High-speed on-chip oscillator		Operation possible
	Low-speed on-chip oscillator	_	Operation possible
	IWDT-dedicated on-chip oscillator	_	Operation possible
	PLL	_	Operation possible
	CPU	_	Stopped (retained)
	RAM0	_	Operation possible
	(0000 0000h to 0000 3FFFh: RX110, 0000 0000h to 0000 FFFFh: RX140)		(retained)
	DTC	_	Operation possible
	Flash memory	_	Stopped (retained)
	Independent watchdog timer (IWDT)	_	Operation possible
	Realtime clock (RTC)	_	Operation possible
	Low-power timer (LPT)	_	Operation possible
	Voltage detection circuit (LVD)	_	Operation possible
	Power-on reset circuit	_	Operation
	Peripheral modules	_	Operation possible
	I/O ports	_	Operation
	RTCOUT output	_	Operation possible
	CLKOUT output	_	Operation possible
	Comparator B	_	Operation possible

Note: "Operation possible" means that whether the state is operating or stopped is controlled by the control register setting.

[&]quot;Stopped (retained)" means that internal register values are retained and internal operations are suspended.

[&]quot;Stopped (undefined)" means that internal register values are undefined and power is not supplied to the internal circuit.

Table 2.12 Comparison of Low Power Consumption Registers

Register	Bit	RX110	RX140
MSTPCRA	MSTPA4	_	8-bit timer 3/2 (unit 1) module stop bit
	MSTPA5	_	8-bit timer 1/0 (unit 0) module stop bit
	MSTPA19	_	D/A converter module stop bit
MSTPCRB	MSTPB0	_	CAN module module stop bit
	MSTPB9	_	ELC module stop bit
	MSTPB10	_	Comparator B module stop bit
	MSTPB25	_	Serial communication interface 6 module stop bit
MSTPCRC		Module stop control register C	Module stop control register C
		Initial value after a reset differs.	
	MSTPC26	_	Serial communication interface 9 module stop bit
	MSTPC27	_	Serial communication interface 8 module stop bit
MSTPCRD		_	Module stop control register D
OPCCR	OPCM[2:0]	Operating power control mode select bits	Operating power control mode select bits
		b2 b0	b2 b0
		0 0 0: High-speed operating mode	0 0 0: High-speed operating mode
		0 1 0: Middle-speed operating mode	0 1 0: Middle-speed operating mode
			1 0 0: Middle-speed operating mode 2
		Settings other than the above are prohibited.	Settings other than the above are prohibited.
SNZCR	_	_	Snooze control register
SNZCR2	_	_	Snooze control register 2

2.8 Register Write Protection Function

Table 2.13 is a comparative overview of the register write protection functions, and Table 2.14 is a comparison of register write protection function registers.

Table 2.13 Comparative Overview of Register Write Protection Functions

Item	RX110	RX140
PRC0 bit	Registers related to the clock generation circuit: SCKCR, SCKCR3, MOSCCR, SOSCCR, LOCOCR, ILOCOCR, HOCOCR, OSTDCR, OSTDSR, CKOCR	Registers related to the clock generation circuit: SCKCR, SCKCR3, PLLCR, PLLCR2, MOSCCR, SOSCCR, LOCOCR, ILOCOCR, HOCOCR, LOFCR, OSTDCR, OSTDSR, CKOCR, LOCOTRR2, ILOCOTRR, HOCOTRR0, SOMCR
PRC1 bit	Register related to the operating modes: SYSCR1 Registers related to the low power consumption functions: SBYCR, MSTPCRA, MSTPCRB, MSTPCRC, OPCCR, RSTCKCR, SOPCCR Registers related to the clock generation circuit: MOFCR, MOSCWTCR Software reset register: SWRR	Register related to the operating modes: SYSCR1 Registers related to the low power consumption functions: SBYCR, MSTPCRA, MSTPCRB, MSTPCRC, MSTPCRD, OPCCR, RSTCKCR, SOPCCR, SNZCR, SNZCR2 Registers related to the clock generation circuit: MOFCR, MOSCWTCR Software reset register: SWRR
PRC2 bit	Registers related to the clock generation circuit: HOCOWTCR	Registers related to the low power timer: LPTCR1, LPTCR2, LPTCR3, LPTPRD, LPCMR0, LPCMR1, LPWUCR
PRC3 bit	Registers related to LVD: LVCMPCR, LVDLVLR, LVD1CR0, LVD1CR1, LVD1SR, LVD2CR0, LVD2CR1, LVD2SR	Registers related to LVD: LVCMPCR, LVDLVLR, LVD1CR0, LVD1CR1, LVD1SR, LVD2CR0, LVD2CR1, LVD2SR

Table 2.14 Comparison of Register Write Protection Function Registers

Register	Bit	RX110	RX140
PRCR	PRC2	Enables writing to the registers related to the clock generation circuit.	Enables writing to the registers related to the low-power timer.

2.9 Exception Handling

Table 2.15 is a comparative overview of exception handling, Table 2.16 is a comparative listing of vectors, and Table 2.17 is a comparative listing of instructions for returning from exception handling routines.

Table 2.15 Comparative Overview of Exception Handling

Item	RX110	RX140
Exception events	Undefined instruction exception	Undefined instruction exception
	Privileged instruction exception	 Privileged instruction exception
		Access exception
		Floating-point exception
	Reset	Reset
	Non-maskable interrupt	Non-maskable interrupt
	Interrupt	Interrupt
	Unconditional trap	Unconditional trap

Table 2.16 Comparative Listing of Vectors

Item		RX110	RX140
Undefined	instruction exception	Fixed vector table	Exception vector table (EXTB)
Privileged i	nstruction exception	Fixed vector table	Exception vector table (EXTB)
Access exc	ception	_	Exception vector table (EXTB)
Floating-po	oint exception	_	Exception vector table (EXTB)
Reset		Fixed vector table	Exception vector table (EXTB)
Non-maska	able interrupt	Fixed vector table	Exception vector table (EXTB)
Interrupt	Fast interrupt	FINTV	FINTV
	Other than fast interrupt	Relocatable vector table (INTB)	Relocatable vector table (INTB)
Unconditio	nal trap	Relocatable vector table (INTB)	Relocatable vector table (INTB)

Table 2.17 Comparative Listing of Instructions for Returning from Exception Handling Routines

Item		RX110	RX140	
Undefined	instruction exception	RTE	RTE	
Privileged	instruction exception	RTE	RTE	
Access exc	ception	_	RTE	
Floating-po	oint exception	_	RTE	
Reset		Return not possible	Return not possible	
Non-maska	able interrupt	Return not possible	Prohibited	
Interrupt	Fast interrupt	RTFI	RTFI	
Other than fast interrupt		RTE	RTE	
Unconditio	nal trap	RTE	RTE	

2.10 Interrupt Controller

Table 2.18 is a comparative overview of the interrupt controllers, and Table 2.19 is a comparison of interrupt controller registers.

Table 2.18 Comparative Overview of Interrupt Controllers

Item		RX110 (ICUb)	RX140 (ICUb)
Interrupts	Peripheral function interrupts	 Interrupts from peripheral modules Interrupt detection: Edge detection/level detection The detection method is fixed for each connected peripheral module source. 	 Interrupts from peripheral modules Interrupt detection: Edge detection/level detection The detection method is fixed for each connected peripheral module source.
	External pin interrupts	 Interrupts from pins IRQ0 to IRQ7 Number of sources: 8 Interrupt detection: Ability to set as source detection of low level, falling edge, rising edge, or rising and falling edges Digital filter function: Supported 	 Interrupts from pins IRQ0 to IRQ7 Number of sources: 8 Interrupt detection: Ability to set as source detection of low level, falling edge, rising edge, or rising and falling edges Digital filter function: Supported
	Software interrupts	Interrupt generated by writing to a register	Interrupt generated by writing to a register
	Event link interrupts	Number of sources: 1 —	Number of sources: 1 An ELSR8I or ELSR18I interrupt can be generated by an ELC event.
			Specified by registers.
	Fast interrupt function	Faster interrupt handling by the CPU can be specified for a single interrupt source only.	Faster interrupt handling by the CPU can be specified for a single interrupt source only.
	DTC control	The DTC can be activated by an interrupt source.	The DTC can be activated by an interrupt source.
Non- maskable interrupts	NMI pin interrupt	 Interrupt from the NMI pin Interrupt detection: Falling edge or rising edge Digital filter function: Supported 	 Interrupt from the NMI pin Interrupt detection: Falling edge or rising edge Digital filter function: Supported
	Oscillation stop detection interrupt	Interrupt on detection of oscillation having stopped	Interrupt on detection of oscillation having stopped
	IWDT underflow/ refresh error interrupt	Interrupt on an underflow of the down counter or occurrence of a refresh error	Interrupt on an underflow of the down counter or occurrence of a refresh error
	Voltage monitoring 1 interrupt	Voltage monitoring interrupt of voltage monitoring circuit 1 (LVD1)	Voltage monitoring interrupt of voltage monitoring circuit 1 (LVD1)
	Voltage monitoring 2 interrupt	Voltage monitoring interrupt of voltage monitoring circuit 2 (LVD2)	Voltage monitoring interrupt of voltage monitoring circuit 2 (LVD2)

Item	RX110 (ICUb)	RX140 (ICUb)
Return from low power consumption state	 Sleep mode and deep sleep mode: Return is initiated by a non-maskable interrupt or any other interrupt source. Software standby mode: Return is initiated by a non-maskable interrupt, interrupt IRQ0 to IRQ7, or an RTC alarm or periodic interrupt. 	 Sleep mode and deep sleep mode: Return is initiated by a non-maskable interrupt or any other interrupt source. Software standby mode: Return is initiated by a non-maskable interrupt, interrupt IRQ0 to IRQ7, or an RTC alarm or periodic interrupt.

Table 2.19 Comparison of Interrupt Controller Registers

Register	Bit	RX110 (ICUb)	RX140 (ICUb)	
IRn*1		Interrupt request register n	, , ,	
		(n = 016 to 249)	(n = 016 to 255)	
IPRn*1		Interrupt source priority register n	Interrupt source priority register n	
		(n = 000 to 249)	(n = 000 to 255)	
DTCERn*1		DTC activation enable register n	DTC transfer request enable register	
		(n = 027 to 248)	n (n = 027 to 255)	

Note: 1. On the RX110 Group n = 250 to 255 correspond to a reserved area.

2.11 Buses

Table 2.20 is a comparative overview of the buses, and Table 2.21 is a comparison of bus registers.

Table 2.20 Comparative Overview of Buses

Bus Type		RX110 RX140	
CPU buses	Instruction bus Operand bus	Connected to the CPU (for instructions) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK) Connected to the CPU (for	Connected to the CPU (for instructions) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK) Connected to the CPU (for
		operands) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK)	operands) Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK)
Memory buses	Memory bus 1	Connected to RAM	Connected to RAM
Internal main buses	Memory bus 2 Internal main bus 1	Connected to ROM Connected to the CPU Operates in synchronization with the system clock (ICLK)	Connected to ROM Connected to the CPU Operates in synchronization with the system clock (ICLK)
	Internal main bus 2	 Connected to the DTC Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK) 	 Connected to the DTC Connected to on-chip memory (RAM, ROM) Operates in synchronization with the system clock (ICLK)
Internal peripheral buses	Internal peripheral bus 1	Connected to peripheral modules (DTC, interrupt controller, and bus error monitoring section) Operates in synchronization with the system clock (ICLK)	 Connected to peripheral modules (DTC, interrupt controller, and bus error monitoring section) Operates in synchronization with the system clock (ICLK)
	Internal peripheral bus 2	 Connected to peripheral modules Operates in synchronization with the peripheral module clock (PCLKB) 	 Connected to peripheral modules Operates in synchronization with the peripheral module clock (PCLKB, PCLKD)
	Internal peripheral bus 3		 Connected to peripheral modules (CTSU, RSCAN0) Operates in synchronization with the peripheral module clock (PCLKB)
	Internal peripheral bus 6	 Connected to ROM (P/E) Operates in synchronization with the FlashIF clock (FCLK) 	Connected to ROM (P/E) and E2 DataFlash Operates in synchronization with the FlashIF clock (FCLK)

Table 2.21 Comparison of Bus Registers

Register	Bit	RX110	RX140
BUSPRI	BPGB[1:0]	Internal peripheral bus 2 priority	Internal peripheral bus 2 and 3
		control bits	priority control bits

2.12 Data Transfer Controller

Table 2.22 is a comparative overview of the data transfer controllers, and Table 2.23 is a comparison of data transfer controller registers.

 Table 2.22
 Comparative Overview of Data Transfer Controllers

Item	RX110 (DTCa)	RX140 (DTCb)
Number of	Equal to number of all interrupt sources	Equal to number of all interrupt sources
transfer channels	that can start a DTC transfer.	that can start a DTC transfer.
Transfer modes	Normal transfer mode A single activation leads to a single data transfer.	Normal transfer mode A single activation leads to a single data transfer.
	Repeat transfer mode A single activation leads to a single data transfer.	 Repeat transfer mode A single activation leads to a single data transfer.
	 The transfer address returns to the transfer start address when the number of data transfers equals the repeat size. 	 The transfer address returns to the transfer start address when the number of data transfers equals the repeat size.
	— The maximum number of repeat transfers is 256, and the maximum data transfer size is 256 x 32 bits, or 1,024 bytes.	 The maximum number of repeat transfers is 256, and the maximum data transfer size is 256 × 32 bits, or 1,024 bytes.
	Block transfer mode	Block transfer mode
	 A single activation leads to the transfer of a single block of data. The maximum block size is 256 × 32 bits = 1,024 bytes. 	 A single activation leads to the transfer of a single block of data. The maximum block size is 256 × 32 bits = 1,024 bytes.
Chain transfer function	 Multiple data transfers can be executed in response to a single transfer request (chain transfer). Either "performed only when the transfer counter reaches 0" or 	 Multiple data transfer types can be executed sequentially in response to a single transfer request. Either "performed only when the transfer counter reaches 0" or "every"
	"performed every time" can be selected for chain transfers.	time" can be selected.
Sequence transfer		A complex series of transfers can be registered as a sequence. Any sequence can be selected by the transfer data and executed.
		 Only one sequence transfer trigger source can be selected at a time. Up to 256 sequences can correspond
		to a single trigger source. The data that is initially transferred in
		response to a transfer request determines the sequence.
		The entire sequence can be executed on a single request, or the sequence can be suspended in the middle and resumed on the next transfer request (sequence division).

Item	RX110 (DTCa)	RX140 (DTCb)
Transfer space	 16 MB in short-address mode (within 0000 0000h to 007F FFFFh or FF80 0000h to FFFF FFFFh, excluding reserved areas) 4 GB in full-address mode (within 0000 0000h to FFFF FFFFh, excluding reserved areas) 	16 MB in short-address mode (within 0000 0000h to 007F FFFFh or FF80 0000h to FFFF FFFFh, excluding reserved areas) 4 GB in full-address mode (within 0000 0000h to FFFF FFFFh, excluding reserved areas)
Data transfer units	 Single data unit: 1 byte (8 bits), 1 word (16 bits), or 1 longword (32 bits) Single block size: 1 to 256 data units 	 Single data unit: 1 byte (8 bits), 1 word (16 bits), or 1 longword (32 bits) Single block size: 1 to 256 data units
CPU interrupt requests	 An interrupt request to the CPU can be generated by a DTC activation interrupt. An interrupt request to the CPU can be generated after a single data transfer. An interrupt request to the CPU can be generated after transfer of the specified number of data units. 	 An interrupt request to the CPU can be generated by a DTC activation interrupt. An interrupt request to the CPU can be generated after a single data transfer. An interrupt request to the CPU can be generated after transfer of the specified number of data units.
Event link function		An event link request is generated after one data transfer (for block transfers, after one block).
Read skip	Transfer information read skipping can be specified.	Reading of the transfer information can be skipped when the same transfer is repeated.
Write-back skip	Write-back can be skipped when the address of the transfer source or destination is fixed.	Write-back of transferred data that is not updated can be skipped when the address of the transfer source or destination is fixed.
Write-back disable	_	Ability to disable write-back of transfer information
Displacement addition	_	Ability to add displacement to the transfer source address (selectable by each transfer information)
Low power consumption function	Ability to specify module stop state	Ability to transition to module stop state

Table 2.23 Comparison of Data Transfer Controller Registers

Register	Bit	RX110 (DTCa)	RX140 (DTCb)	
MRA	WBDIS	_	Write-back disable bit*1	
MRB	SQEND	_	Sequence transfer end bit	
	INDX	<u> </u>	Index table reference bit	
MRC	_	_	DTC mode register C	
DTCIBR	_	<u> </u>	DTC index table base register	
DTCOR	_	_	DTC operation register	
DTCSQE	_		DTC sequence transfer enable	
			register	
DTCDISP		_	DTC address displacement register	

Note: 1. Transfer information is usually allocated to a RAM area, but it can be allocated to a ROM area by setting the MRA.WBDIS bit to 1 (no write-back).

2.13 I/O Ports

Table 2.24 and Table 2.25 are comparative overviews of the I/O ports, Table 2.26 is a comparison of I/O port functions, and Table 2.27 is a comparison of I/O port registers.

Table 2.24 Comparative Overview of I/O Ports (64-Pin)

Port Symbol	RX110 (64-Pin) RX140 (64-Pin)		
PORT0	P03, P05 P03, P05		
PORT1	P14 to P17	P14 to P17	
PORT2	P26, P27	P26, P27	
PORT3	P30 to P32, P35	P30 to P32, P35 to P37	
PORT4	P40 to P44, P46	P40 to P47	
PORT5	P54, P55	P54, P55	
PORTA	PA0, PA1, PA3, PA4, PA6 PA0, PA1, PA3, PA4, PA6		
PORTB	PB0, PB1, PB3, PB5 to PB7 PB0, PB1, PB3, PB5 to PB7		
PORTC	PC2 to PC7 PC0 to PC7		
PORTE	PE0 to PE7 PE0 to PE5		
PORTG	PG7		
PORTH	PH0 to PH3 PH6*1, PH7*1		
PORTJ	PJ6, PJ7	PJ6, PJ7	

Note: 1. A product with a ROM capacity of 64 KB is not equipped with this pin.

Table 2.25 Comparative Overview of I/O Ports (48-Pin)

Port Symbol	RX110 (48-Pin) RX140 (48-Pin)		
PORT1	P14 to P17	P14 to P17	
PORT2	P26, P27	P26, P27	
PORT3	P35	P30, P31, P35 to P37	
PORT4	P40 to P42, P46	P40 to P42, P45 to P47	
PORTA	PA1, PA3, PA4, PA6	PA1, PA3, PA4, PA6	
PORTB	PB0, PB1, PB3, PB5	PB0, PB1, PB3, PB5	
PORTC	PC4 to PC7	PC0 to PC7	
PORTE	PE0 to PE4, PE7	PE1 to PE4	
PORTG	_	PG7	
PORTH	PH0 to PH3	PH0 to PH3	
PORTJ	PJ6, PJ7	PJ6, PJ7	

Table 2.26 Comparison of I/O Port Functions

Item	Port Symbol	RX110	RX140
Input pull-up function	PORT0	P03, P05	P03 to P07
	PORT1	P14, P15, P16, P17	P12 to P17
	PORT2	P26, P27	P20, P21, P26, P27
	PORT3	P30 to P32	P30 to P32, P34, P36, P37
	PORT4	_	P40 to P47
	PORT5	P54, P55	P54, P55
	PORTA	PA0, PA1, PA3, PA4, PA6	PA0 to PA6
	PORTB	PB0, PB1, PB3, PB5 to PB7	PB0 to PB7
	PORTC	PC0 to PC7	PC2 to PC7
	PORTD	_	PD0 to PD2
	PORTE	PE0 to PE7	PE0 to PE3, PE4, PE5
	PORTG	_	PG7
	PORTH	PH0 to PH3	PH0 to PH3
	PORTJ	_	PJ1, PJ6, PJ7
Open drain output	PORT1	P14 to P17	P12 to P17
function	PORT2	P26, P27	P20, P21, P26, P27
	PORT3	P30 to P32	P30 to P32, P34, P36, P37
	PORTA	PA0, PA1, PA3, PA4, PA6	PA0 to PA6
	PORTB	PB0, PB1, PB3, PB5 to PB7	PB0 to PB7
	PORTC	PC0 to PC7	PC2 to PC7
	PORTD	_	PD0 to PD2
	PORTE	PE0 to PE7	PE0 to PE3
	PORTG	<u> </u>	PG7
5 V tolerant	PORT1	P16, P17	P12, P13, P16, P17
	PORTA	PA6	_
	PORTB	PB0	

Table 2.27 Comparison of I/O Port Registers

Register	Bit	RX110	RX140
PDR	B0 to B7	Pm0 to Pm7 direction control bits	Pm0 to Pm7 direction control bits
		(m = 0 to 5, A to C, E, H, J)	(m = 0 to 5, A to E, G, H, J)
PODR	B0 to B7	Pm0 to Pm7 output data store bits	Pm0 to Pm7 output data store bits
		(m = 0 to 5, A to C, E, H, J)	(m = 0 to 5, A to E, G, H, J)
PIDR	B0 to B7	Pm0 to Pm7 bits	Pm0 to Pm7 bits
		(m = 0 to 5, A to C, E, H, J)	(m = 0 to 5, A to E, G, H, J)
PMR	B0 to B7	Pm0 pin mode control bits	Pm0 pin mode control bits
		(m = 0 to 5, A to C, E, H, J)	(m = 0 to 5, A to E, G, H, J)
		0: Use pin as general I/O port.	0: Use pin as general I/O port.
		1: Use pin as I/O port for peripheral	1: Use pin as I/O port for peripheral
		function.	function.
			PG7 only
			0: Use pin as general I/O port.
			1: Use pin as I/O port for MD
			function (initial value).

Register	Bit	RX110	RX140
ODR0	B0, B4, B6	Pm0, Pm2, and Pm3 output type select bits (m = 3, A to C, E)	Pm0, Pm2, and Pm3 output type select bits (m =1 to 3, A to E, J)
	B2, B3	Pm1 output type select bits (m = 3, A to C, E)	Pm1 output type select bits (m =1 to 3, A to E, J)
		• P31, PA1, PB1, and PC1 b2	• P21, P31, PA1, PB1, and PD1 b2
		0: CMOS output	0: CMOS output
		1: N-channel open-drain	1: N-channel open-drain
		b3	b3
		This bit is read as 0. The write value should be 0.	This bit is read as 0. The write value should be 0.
		• PE1	• PE1
		b3 b2	b3 b2
		0 0: CMOS output	0 0: CMOS output
		0 1: N-channel open-drain 1 0: P-channel open-drain	0 1: N-channel open-drain 1 0: P-channel open-drain
		1 1: Setting prohibited	1 1: Hi-Z
ODR1	B0, B1 (RX110)	Pm4 output type select bits	Pm4 output type select bits
	B0 (RX140)	(m = 1, 2, A to C, E)	(m = 1 to 3, A to C, G)
		DA4 DO4 == 4 DE4	
		• PA4, PC4, and PE4 b0	b0
		0: CMOS output	0: CMOS output
		1: N-channel open-drain	1: N-channel open-drain
		b1	'
		This bit is read as 0. The write	
		value should be 0.	
		• P14	
		b1 b0	
		0 0: CMOS output	
		0 1: N-channel open-drain	
		1 0: P-channel open-drain	
		1 1: Setting prohibited	
	B2, B4, B6	Pm5, Pm6, and Pm7 output type select bits	Pm5, Pm6, and Pm7 output type select bits
		(m = 1, 2, A to C, E)	(m = 1 to 3, A to C, G)
PCR	B0 to B7	Pm0 to Pm7 input pull-up resistor	Pm0 to Pm7 input pull-up resistor
		control bits	control bits
		(m = 0 to 3, 5, A to C, E, H)	(m = 0 to 5, A to E, G, H, J)
PRWCNTR	_	<u> </u>	Port read wait control register

2.14 Multi-Function Pin Controller

Table 2.28 is a comparison of the assignments of multiplexed pins, and Table 2.29 to Table 2.41 are comparisons of multi-function pin controller registers.

In the following comparison of the assignments of multiplexed pins, blue text designates pins that exist on the RX140 Group only and orange text pins that exist on the RX110 Group only. A circle (\bigcirc) indicates that a function is assigned, a cross (\times) that the pin does not exist or that no function is assigned, and grayed out items mean that the function is not implemented.

Table 2.28 Comparison of Multiplexed Pin Assignments

Module/		Port	RX110		RX140	
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Interrupt	NMI (input)	P35	0	0	0	0
	IRQ0 (input)	P30	0	×	0	0
		PE0	0	0	×	×
		PH1	0	0	0	0
	IRQ1 (input)	P31	0	×	0	0
		PE1	0	0	×	×
		PH2	0	0	0	0
	IRQ2 (input)	P32	0	×	0	×
		PB0	0	0	×	×
		PC4	0	0	×	×
		P36	X	×	0	0
	IRQ3 (input)	P27	0	0	×	×
		PE3	0	0	×	×
		PA6	0	0	×	×
	IRQ4 (input)	P14	0	0	0	0
		PB1	0	0	0	0
		PE4	0	0	×	×
		P37	X	×	0	0
	IRQ5 (input)	P15	0	0	0	0
		PA4	0	0	0	0
		PE5	0	×	0	×
	IRQ6 (input)	P16	0	0	0	0
		PA3	0	0	0	0
		PE6	0	×	×	×
	IRQ7 (input)	P17	0	0	0	0
		PE2	0	0	0	0
		PE7	0	0	×	×
Multi-function	MTIOC0A	P14	0	0	×	×
timer unit 2	(input/output)	PB3	0	0	0	0
		PE3	0	0	×	×
		PC4	X	×	0	0
	MTIOC0B	P15	0	0	0	0
	(input/output)	PA1	0	0	0	0
	MTIOC0C	P17	0	0	X	×
	(input/output)	P32	0	X	0	×
		PB0	0	0	X	×
		PB1	0	0	0	0
		PC5	X	X	0	0
	MTIOC0D (input/output)	PA3	0	0	0	0

Module/		Port	RX110		RX140		
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin	
Multi-function	MTIOC1A	PE4	0	0	0	0	
timer unit 2	(input/output)	PH3	0	0	×	×	
	MTIOC1B	PA3	0	0	×	×	
	(input/output)	PB5	0	0	0	0	
		PE3	0	0	0	0	
		PH0	0	0	×	×	
	MTIOC2A	P26	0	0	0	0	
	(input/output)	PA6	0	0	×	×	
l		PB5	0	0	0	0	
l		PE0	0	0	×	×	
l	MTIOC2B	P27	0	0	0	0	
l	(input/output)	PA4	0	0	×	×	
l		PE5	0	×	0	×	
l	MTIOC3A	P14			0	0	
l	(input/output)	P17			0	0	
l		PC7			0	0	
	MTIOC3B	P17			0	0	
l	(input/output)	PA1			0	0	
		PB7			0	×	
		PC5			0	0	
l		PH0			0	0	
	MTIOC3C	P16			0	0	
	(input/output)	PC6			0	0	
	MTIOC3D	P16			0	0	
l	(input/output)	PA6			0	0	
l		PB0			0	0	
l		PB6			0	×	
l		PC4			0	0	
		PH1			0	0	
	MTIOC4A	P55			0	X	
	(input/output)	PA0			0	×	
		PB3			0	0	
l		PE2			0	0	
		PE4			0	0	
l	MTIOC4B	P30			0	0	
	(input/output)	P54			0	×	
		PC2			0	×	
		PE3			0	0	
l	MTIOC4C	PA4			0	0	
l	(input/output)	PB1			0	0	
l		PE1			0	0	
1		PE5			O	×	
		PH2			O	0	
	MTIOC4D	P31			O	0	
	(input/output)	P55			O	×	
		PA3			0	Ô	
		PC3			0	X	
		PE4			0	Ô	
	1				0	0	
		PH3					

Module/		Port	Port RX110		RX140		
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin	
Multi-function timer unit 2	MTIC5V (input)	PA6	0	0	0	0	
		PA3	X	X	0	0	
	MTIC5W (input)	PB0	0	0	0	0	
	MTCLKA (input)	P14	0	0	0	0	
		PA4	0	0	0	0	
		PC6	0	0	0	0	
	MTCLKB (input)	P15	0	0	0	0	
		PA6	0	0	0	0	
		PC7	0	0	0	0	
	MTCLKC (input)	PA1	0	0	0	0	
	NITOLICO (I	PC4	0	0	0	0	
	MTCLKD (input)	PA3	0	0	0	0 0	
0	DVD4 (' · · · · · ·) /	PC5	0	0	0	00	
Serial communications	RXD1 (input) / SMISO1	P15	_	0	_	_	
interface	(input/output) /	P30	0	×	0	0	
monaco	SSCL1 (input/output)	PC6	0	0	X	×	
	TXD1 (output) /	P16	0	0	0	0	
	SMOSI1 (input/output) /	P26	0	0	0	0	
	SSDA1 (input/output)	PC7	0	0	×	X	
	SCK1 (input/output)	P17	0	0	0	0	
		P27	0	0	0	0	
		PC5	0	0	×	×	
	CTS1# (input) / RTS1# (output) / SS1# (input)	P14	0	0	0	0	
		P31	0	×	0	0	
	RXD5 (input) / SMISO5	PA3	0	0	0	0	
	(input/output) / SSCL5 (input/output)	PC2	0	×	0	×	
	TXD5 (output) / SMOSI5	PA4	0	0	0	0	
	(input/output) / SSDA5 (input/output)	PC3	0	×	0	×	
	SCK5 (input/output)	PA1	0	0	0	0	
		PC4	0	0	0	0	
	CTS5# (input) / RTS5# (output) / SS5# (input)	PA6	0	0	0	0	
	RXD6 (input) / SMISO6 (input/output) / SSCL6 (input/output)	PB0			*1	*1	
	TXD6 (output) / SMOSI6	P32			O*1	×	
	(input/output) / SSDA6 (input/output)	PB1			O*1	<u></u> *1	
	SCK6 (input/output)	PB3			O*1	O*1	

Module/	Pin Function	Port	RX110		RX140	
Function		Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Serial	RXD8 (input) /	PC6			O*1	O *1
communications interface	SMISO8					
	(input/output) /					
	SSCL8 (input/output)	50-			0.4	0.1
	TXD8 (output) / SMOSI8	PC7			O *1	O *1
	(input/output) /					
	SSDA8 (input/output)					
	SCK8 (input/output)	PC5			O*1	O*1
	CTS8# (input) /	PC4			O*1	O *1
	RTS8# (output) /					
	SS8# (input)					
	RXD9 (input) /	PB6			O *1	×
	SMISO9					
	(input/output) /					
	SSCL9 (input/output)					
	TXD9 (output) /	PB7			O*1	×
	SMOSI9					
	(input/output) / SSDA9 (input/output)					
	SCK9 (input/output)	PB5			O*1	×
	CTS9# (input) /	PB4			O*1	X
	RTS9# (output) /	1 54				
	SS9# (input)					
	SCK12 (input/output)	PE0	0	0	0	×
		P27	0	0	×	×
	RXD12 (input) /	PE2	0	0	0	O *3
	SMISO12					
	(input/output) /		_	_		
	SSCL12	P17	0	0	X	×
	(input/output) / RXDX12 (input)					
	TXD12 (output) /	PE1	0	0	0	O *4
	SMOSI12	1 - 1				
	(input/output) /					
	SSDA12	D4.4			\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
	(input/output) /	P14	0	0	×	×
	TXDX12 (output) /					
	SIOX12 (input/output)					
	CTS12# (input) /	PE3	0	0	0	O *5
	RTS12# (output) /					
I ² C bus interface	SS12# (input) SCL0 (input/output)	P16	0	0	0	0
i C bus iliteriace	SOLO (iriput/output)	PB0	0	0		X
	SDA0 (input/output)	P17	0	0	X	0
	SDAO (Iriparoatpat)	PA6	0	0		X
		FAU			X	_ ^

Module/		Port	RX110 RX140			
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Serial peripheral	RSPCKA	P15	0	0	X	×
interface	(input/output)	PB0	0	0	0	0
		PC5	0	Ö	0	0
		PE3	0	Ō	X	×
	MOSIA (input/output)	P16	0	Ō	0	0
		PA6	0	0	0	0
		PE4	0	O	X	×
		PC6	0	0	0	0
	MISOA (input/output)	P17	0	0	0	0
		PC7	0	0	0	0
		PA3	0	0	×	×
	SSLA0 (input/output)	P14	O	0	×	×
		PA4	0	0	0	0
		PC4	0	0	0	0
	SSLA1 (output)	PA0	0	X	0	X
	SSLA2 (output)	PA1	0	0	0	0
	SSLA3 (output)	PC2	0	X	0	×
Realtime clock	RTCOUT (output)	P16	0	0	0	0
		P32	0	×	0	×
		PB0	0	0	×	×
		PA1	0	0	×	×
12-bit A/D	AN000 (input)*2	P40	0	0	0	0
converter	AN001 (input)*2	P41	0	0	0	0
	AN002 (input)*2	P42	0	0	0	0
	AN003 (input)*2	P43	0	×	0	×
	AN004 (input)*2	P44	0	×	0	×
	AN005 (input)*2	P45			0	0
	AN006 (input)*2	P46	0	0	0	0
	AN007 (input)*2	P47			0	0
	AN008 (input)*2	PE0	0	0		
	AN009 (input)*2	PE1	0	0		
	AN010 (input)*2	PE2	0	0		
	AN011 (input)*2	PE3	0	0		
	AN012 (input)*2	PE4	0	0		
	AN013 (input)*2	PE5	0	×		
	AN014 (input)*2	PE6	0	X		
	AN015 (input)*2	PE7	0	0		
	AN016 (input)*2	PE0			0	×
	AN017 (input)*2	PE1			0	0
	AN018 (input)*2	PE2			0	0
	AN019 (input)*2	PE3			0	0
	AN020 (input)*2	PE4			0	0
	AN021 (input)*2	PE5			0	×
	VREFH0 (input)	PJ6	0	0		
	VREFL0 (input)	PJ7	0	0		
	ADTRG0# (input)	P16	0	0	0	0
		P27	0	0	X	×
		PB0	0	0	X	×

Module/		Port	RX110		RX140	
Function	Pin Function	Allocation	64-Pin	48-Pin	64-Pin	48-Pin
Clock	CLKOUT (output)	P15	0	0	X	×
generation		PC4	O	0	X	×
circuit		PE3	X	×	0	0
		PE4	X	×	0	O
Clock frequency	CACREF (input)	P27	0	0	X	×
accuracy		PA0	0	×	0	×
measurement		PC7	0	0	0	0
circuit		PH0	0	0	0	0
Voltage	CMPA2 (input)*2	P27	O	0	X	X
detection circuit		PE4	X	×	O	0
Port output	POE0# (input)	PC4			O	O
enable 2	POE1# (input)	PB5			0	0
	POE2# (input)	PA6			0	Ō
	POE3# (input)	PB3			0	0
	POE8# (input)	P17			0	0
	()	P30			0	O
		PE3			O	O
8-bit timer	TMO0 (output)	PB3			O	O
	·····co (carpai)	PH1			0	O
	TMCI0 (input)	PB1			0	O
	()	PH3			0	Ö
	TMRI0 (input)	PA4			0	O
	i i i i i i i i i i i i i i i i i i i	PH2			0	O
	TMO1 (output)	P17			0	0
	Timo ((output)	P26			0	0
	TMCI1 (input)	P54			0	×
	imorr (impat)	PC4			0	Ô
	TMRI1 (input)	PB5			0	O
	TMO2 (output)	P16			0	0
	TWO2 (Galpat)	PC7			0	0
	TMCI2 (input)	P15			0	O
	imoiz (input)	P31			0	0
		PC6			0	O
	TMRI2 (input)	P14			0	0
	TWI (II pat)	PC5			0	0
	TMO3 (output)	P32			0	×
	Times (surpur)	P55			0	×
	TMCI3 (input)	P27			0	Ö
	Twois (input)	PA6			0	0
	TMRI3 (input)	P30			0	0
Low-power	LPTO (output)	P26			0	0
timer	_i · O (output)	PB3			0	0
		PC7			0	0
CAN module	CTXD0 (output)	P14			O*1	O*1
CAN IIIOUUIE	OTADO (output)	P54			O *1	X
	CRXD0 (input)	P15			O *1	
	OTADO (Iliput)	P55			O*1	X
D/A converter	DA0 (output)*2	P03			0*1	X
DIA CONverter						
	DA1 (output)*2	P05			0	×

Function Comparator B	Pin Function CMPB0 (input)*2	Allocation	64-Pin	48-Pin	64-Pin	
Comparator B	` ` ` /		•	70-1 111	04-FIII	48-Pin
		PE1			0	0
	CVREFB0 (input)*2	PE2			0	0
	CMPOB0 (output)	PE5			0	×
	CMPB1 (input)*2	PA3			0	0
	CVREFB1 (input)*2	PA4			0	0
	CMPOB1 (output)	PB1			0	0
Capacitive	TS0 (input/output)	P32			O*1	×
touch sensing	TS1 (input/output)	P31			O*1	O *1
unit	TS2 (input/output)	P30			O*1	O *1
	TS3 (input/output)	P27			0	0
	TS4 (input/output)	P26			0	0
	TS5 (input/output)	P15			O*1	O *1
	TS6 (input/output)	P14			O *1	O *1
	TS7 (input/output)	PH3			O*1	O *1
	TS8 (input/output)	PH2			O*1	O *1
	TS9 (input/output)	PH1			O*1	O *1
	TS10 (input/output)	PH0			O*1	O*1
	TS11 (input/output)	P55			O*1	×
	TS12 (input/output)	P54			O*1	×
	TS13 (input/output)	PC7			0	0
	TS14 (input/output)	PC6			0	0
	TS15 (input/output)	PC5			0	0
	TS16 (input/output)	PC3			O*1	×
	TS17 (input/output)	PC2			O*1	×
	TS18 (input/output)	PB7			O*1	×
	TS19 (input/output)	PB6			O*1	×
	TS20 (input/output)	PB5			O*1	O*1
	TS22 (input/output)	PB3			O*1	O*1
	TS24 (input/output)	PB1			O*1	O *1
	TS25 (input/output)	PB0			0	0
	TS26 (input/output)	PA6			O*1	0
	TS28 (input/output)	PA4			0	0
	TS29 (input/output)	PA3			O	Ō
	TS31 (input/output)	PA1			0	Ō
	TS32 (input/output)	PA0			O*1	X
	TS33 (input/output)	PE4			0	0
	TS34 (input/output)	PE3			0	0
	TS35 (input/output)	PE2			0	0
	TSCAP (—)	PC4			0	Ö

Notes: 1. This function is not implemented on RX140 Group products with ROM capacity of 64 KB.

- 2. To use these pin functions, set the relevant pins as general I/O ports (PORT.PDR.Bm and PORT.PMR.Bm bits both cleared to 0).
- 3. The SMISO12 function is not implemented on 48-pin package products.
- 4. The SMOSI12 function is not implemented on 48-pin package products.
- 5. The SS12# function is not implemented on 48-pin package products.

Table 2.29 Comparison of P0n Pin Function Control Register (P0nPFS)

Register	Bit	RX110	RX140 (n = 3, 5, 7)
P0nPFS			P0n pin function control register

Table 2.30 Comparison of P1n Pin Function Control Register (P1nPFS)

Register	Bit	RX110 (n = 4 to 7)	RX140 (n = 2 to 7)
P12PFS		_	P12 pin function control register
P13PFS		_	P13 pin function control register
P14PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3A
		00010b: MTCLKA	00010b: MTCLKA
		00011b: MTIOC0A	
			00101b: TMRI2
		01011b: CTS1#/RTS1#/SS1#	01011b: CTS1#/RTS1#/SS1#
		01100b: TXD12/SMOSI12/SSDA12/ TXD12/SIOX12	
		01101b: SSLA0	
			11001b: TS6
			11100b: CTXD0
P15PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0B	00001b: MTIOC0B
		00010b: MTCLKB	00010b: MTCLKB
			00101b: TMCl2
		01001b: CLKOUT	
		01010b: RXD1/SMISO1/SSCL1	01010b: RXD1/SMISO1/SSCL1
		01101b: RSPCKA	
			11001b: TS5
			11100b: CRXD0
P16PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3C
			00010b: MTIOC3D
			00101b: TMO2
		00111b: RTCOUT	00111b: RTCOUT
		01001b: ADTRG0#	01001b: ADTRG0#
		01010b: TXD1/SMOSI1/SSDA1	01010b: TXD1/SMOSI1/SSDA1
		01101b: MOSIA	01101b: MOSIA
		01111b: SCL0	01111b: SCL



Register	Bit	RX110 (n = 4 to 7)	RX140 (n = 2 to 7)
P17PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3A
			00010b: MTIOC3B
		00011b: MTIOC0C	
			00101b: TMO1
			00111b: POE8#
		01010b: SCK1	01010b: SCK1
		01100b: RXD12/SMISO12/	
		SSCL12/RXDX12	
		01101b: MISOA	01101b: MISOA
		01111b: SDA0	01111b: SDA0
P1nPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
			P12: IRQ2 (80-pin)
			P13: IRQ3 (80-pin)
		P14: IRQ4 (64/48/40/36-pin)	P14: IRQ4 (80/64/48-pin)
		P15: IRQ5 (64/48/40/36-pin)	P15: IRQ5 (80/64/48-pin)
		P16: IRQ6 (64/48/40/36-pin)	P16: IRQ6 (80/64/48/32-pin)
		P17: IRQ7 (64/48/40/36-pin)	P17: IRQ7 (80/64/48/32-pin)

Table 2.31 Comparison of P2n Pin Function Control Register (P2nPFS)

Register	Bit	RX110 (n = 6, 7)	RX140 (n = 0, 1, 6, 7)
P20PFS		_	P20 pin function control register
P21PFS		_	P21 pin function control register
P26PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC2A	00001b: MTIOC2A
			00101b: TMO1
		01010b: TXD1/SMOSI1/SSDA1	01010b: TXD1/SMOSI1/SSDA1
			11001b: TS4
			11011b: LPTO
P27PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC2B	00001b: MTIOC2B
			00101b: TMCl3
		00111b: CACREF	
		01001b: ADTRG0#	
		01010b: SCK1	01010b: SCK1
		01100h; CCV12	
		01100b: SCK12	11001b; TC2
DO»DEC	ICEL	Intervent inner trunction colors bit	11001b: TS3
P2nPFS	ISEL	Interrupt input function select bit	_
	ASEL	Analog function select bit	<u> </u>

Table 2.32 Comparison of P3n Pin Function Control Register (P3nPFS)

Register	Bit	RX110 (n = 0 to 2)	RX140 (n = 0 to 2, 4, 6, 7)
P30PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4B
			00101b: TMRI3
			00111b: POE8#
		01010b: RXD1/SMISO1/SSCL1	01010b: RXD1/SMISO1/SSCL1
			11001b: TS2
P31PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
			200001 111 7
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4D
		04.044h, 070#4/070#4/004#	00101b: TMCl2
		01011b: CTS#1/RTS#1/SS1#	01011b: CTS#1/RTS#1/SS1#
P32PFS	DCEL [4:0]	Pin function select bits	11001b: TS1 Pin function select bits
P32PF3	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOCOC	00001b: MTIOC0C
		000015. W110000	00101b: TMO3
		00111b: RTCOUT	00111b: RTCOUT
			01011b: TXD6/SMOSI6/SSDA6
			11001b: TS0
P34PFS		_	P34 pin function control register
P36PFS		_	P36 pin function control register
P37PFS	_	_	P37 pin function control register
P3nPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		P30: IRQ0 (64-pin)	P30: IRQ0 (80/64/48/32-pin)
		P31: IRQ1 (64-pin)	P31: IRQ1 (80/64/48/32-pin)
		P32: IRQ2 (64-pin)	P32: IRQ2 (80/64-pin)
			P34: IRQ4 (80-pin)
			P36: IRQ2 (80/64/48/32-pin)
			P37: IRQ4 (80/64/48-pin)

Table 2.33 Comparison of P4n Pin Function Control Register (P4nPFS)

Register	Bit	RX110 (n = 0 to 4, 6)	RX140 (n = 0 to 7)
P4nPFS	ASEL	Analog function select bit	Analog function select bit
		0: Used as other than as analog pin	0: Used as other than as analog pin
		1: Used as analog pin	1: Used as analog pin
		P40: AN000 (64/48-pin)	P40: AN000 (80/64/48/32-pin)
		P41: AN001 (64/48/40/36-pin)	P41: AN001 (80/64/48/32-pin)
		P42: AN002 (64/48/40/36-pin)	P42: AN002 (80/64/48/32-pin)
		P43: AN003 (64-pin)	P43: AN003 (80/64-pin)
		P44: AN004 (64-pin)	P44: AN004 (80/64-pin)
			P45: AN005 (80/64/48-pin)
		P46: AN006 (64/48/40-pin)	P46: AN006 (80/64/48-pin)
			P47: AN007 (80/64/48-pin)

Table 2.34 Comparison of P5n Pin Function Control Register (P5nPFS)

Register	Bit	RX110	RX140 (n = 4, 5)
P5nPFS		_	P5n pin function control register

Table 2.35 Comparison of PAn Pin Function Control Register (PAnPFS)

Register	Bit	RX110 (n = 0, 1, 3, 4, 6)	RX140 (n = 0 to 6)
PA0PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4A
		00111b: CACREF	00111b: CACREF
		01101b: SSLA1	01101b: SSLA1
			11001b: TS32
PA1PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0B	00001b: MTIOC0B
		00010b: MTCLKC	00010b: MTCLKC
			00011b: MTIOC3B
		00111b: RTCOUT	
		01010b: SCK5	01010b: SCK5
		01101b: SSLA2	01101b: SSLA2
			11001b: TS31
PA2PFS		_	PA2 pin function control register
PA3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		000001 11: 7	000001 11: 7
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOCOD	00001b: MTIOC0D
		00010b: MTCLKD	00010b: MTCLKD
		00011b: MTIOC1B	00011b: MTIOC4D
		0.404.01 D.V.D.T.(0.110.0.7.(0.5); -	00100b: MTIC5V
		01010b: RXD5/SMISO5/SSCL5	01010b: RXD5/SMISO5/SSCL5
		01101b: MISOA	110011 7000
			11001b: TS29

Register	Bit	RX110 (n = 0, 1, 3, 4, 6)	RX140 (n = 0 to 6)
PA4PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIC5U	00001b: MTIC5U
		00010b: MTCLKA	00010b: MTCLKA
		00011b: MTIOC2B	00011b: MTIOC4C
			00101b: TMRI0
		01010b: TXD5/SMOSI5/SSDA5	01010b: TXD5/SMOSI5/SSDA5
		01101b: SSLA0	01101b: SSLA0
			11001b: TS28
PA5PFS		_	PA5 pin function control register
PA6PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIC5V	00001b: MTIC5V
		00010b: MTCLKB	00010b: MTCLKB
		00011b: MTIOC2A	00011b: MTIOC3D
			00101b: TMCl3
			00111b: POE2#
		01011b: CTS5#/RTS5#/SS5#	01011b: CTS5#/RTS5#/SS5#
		01101b: MOSIA	01101b: MOSIA
		01111b: SDA0	
			11001b: TS26
PAnPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		PA3: IRQ6 (64/48/40/36-pin)	PA3: IRQ6 (80/64/48/32-pin)
		PA4: IRQ5 (64/48/40/36-pin)	PA4: IRQ5 (80/64/48/32-pin)
		PA6: IRQ3 (64/48/40/36-pin)	
	ASEL	_	Analog function select bit

Table 2.36 Comparison of PBn Pin Function Control Register (PBnPFS)

Register	Bit	RX110 (n = 0, 1, 3, 5 to 7)	RX140 (n = 0 to 7)
PB0PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIC5W	00001b: MTIC5W
		00010b: MTIOC0C	00010b: MTIOC3D
		00111b: RTCOUT	
		01001b: ADTRG0#	
			01011b: RXD6/SMISO6/SSCL6
		01101b: RSPCKA	01101b: RSPCKA
		01111b: SCL0	
			11001b: TS25

Register	Bit	RX110 (n = 0, 1, 3, 5 to 7)	RX140 (n = 0 to 7)
PB1PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0C	00001b: MTIOC0C
			00010b: MTIOC4C
			00101b: TMCI0
			01011b: TXD6/SMOSI6/SSDA6
			10000b: CMPOB1
			11001b: TS24
PB2PFS	_		PB2 pin function control register
PB3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
. 50 6	. 022[0]		This range of colocy site
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC0A	00001b: MTIOC0A
		000015. W1100011	00010b: MTIOC4A
			00101b: TMO0
			00111b: POE3#
			01011b: SCK6
			11001b: TS22
			11011b: LPTO
PB4PFS			PB4 pin function control register
PB5PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
FBSF13	F 3LL[4.0]	Fill fullction select bits	Fill full ction select bits
		00000b: Hi-Z	00000b: Hi-Z
		00000b: 111-2 00001b: MTIOC2A	00001b: MTIOC2A
		00010b: MTIOC1B	00010b: MTIOC1B
		00010b. WITIOCIB	00101b: TMRI1
			00101b. HMR11 00111b: POE1#
			01010b: SCK9
			11001b: TS20
DDCDEC	DCEL [4:0]	Pin function select bits	Pin function select bits
PB6PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000h. U: 7	00000h; H; 7
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3D
			01010b: RXD9/SMISO9/SSCL9 11001b: TS19
DDZDEO	DOEL [4:0]	Die ferration calcut hits	
PB7PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		000006.15.7	00000h. H: 7
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3B
			01010b: TXD9/SMOSI9/SSDA9
DD - D50	1051	Little and the second second	11001b: TS18
PBnPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0 Not as les 170 de 1	0. Net 20150
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		PB0: IRQ2 (64/48/40/36-pin)	
		PB1: IRQ4 (64/48-pin)	PB1: IRQ4 (80/64/48-pin)

Table 2.37 Comparison of PCn Pin Function Control Register (PCnPFS)

Register	Bit	RX110 (n = 2 to 7)	RX140 (n = 2 to 7)
PC2PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4B
		01010b: RXD5/SMISO5/SSCL5	01010b: RXD5/SMISO5/SSCL5
		01101b: SSLA3	01101b: SSLA3
			11001b: TS17
PC3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		000005.111-2	00000b: MTIOC4D
		01010b: TXD5/SMOSI5/SSDA5	01010b: TXD5/SMOSI5/SSDA5
		01010b. 1705/5W0515/5500A5	11001b: TS16
PC4PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
1 04110	1 322[4.0]	Till full clion select bits	1 III Idilotion select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3D
		00010b: MTCLKC	00010b: MTCLKC
			00011b: MTIOC0A
			00101b: TMCI1
			00111b: POE0#
		01001b: CLKOUT	
		01010b: SCK5	01010b: SCK5
			01011b: CTS8#/RTS8#/SS8#
		01101b: SSLA0	01101b: SSLA0
			11001b: TSCAP
PC5PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3B
		00010b: MTCLKD	00010b: MTCLKD
			00011b: MTIOC0C
			00101b: TMRI2
			01010b: SCK8
		01011b: SCK1	
		01101b: RSPCKA	01101b: RSPCKA
			11001b: TS15
PC6PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000h; Hi 7
		00000b. HI-Z	00000b: Hi-Z
		00010b: MTCL KA	00001b: MTIOC3C
		00010b: MTCLKA	00010b: MTCLKA
			00101b: TMCl2
		04044b; DVD4/CMICO4/CCCL4	01010b: RXD8/SMISO8/SSCL8
		01011b: RXD1/SMISO1/SSCL1	01101b; MOSIA
		01101b: MOSIA	01101b: MOSIA
			11001b: TS14

Register	Bit	RX110 (n = 2 to 7)	RX140 (n = 2 to 7)
PC7PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3A
		00010b: MTCLKB	00010b: MTCLKB
			00101b: TMO2
		00111b: CACREF	00111b: CACREF
			01010b: TXD8/SMOSI8/SSDA8
		01011b: TXD1/SMOSI1/SSDA1	
		01101b: MISOA	01101b: MISOA
			11001b: TS13
			11011b: LPTO
PCnPFS	ISEL	Interrupt input function select bit	_

Table 2.38 Comparison of PDn Pin Function Control Register (PDnPFS)

Register	Bit	RX110	RX140 (n = 0 to 2)
PDnPFS		_	PDn pin function control register

Table 2.39 Comparison of PEn Pin Function Control Register (PEnPFS)

Register	Bit	RX110 (n = 0 to 7)	RX140 (n = 0 to 5)
PE0PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00010b: MTIOC2A	
_		01100b: SCK12	01100b: SCK12
PE1PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		000001 11: 7	000001 11: 7
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4C
		01100b: TXD12/SMOSI12/SSDA12/ TXDX12/SIOX12	01100b: TXD12/SMOSI12/SSDA12/ TXDX12/SIOX12
DEODEO	DOEL [4:0]		Pin function select bits
PE2PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		000000.1112	00001b: MTIOC4A
		01100b: RXD12/SMISO12/	01100b: RXD12/SMISO12/
		SSCL12/RXDX12	SSCL12/RXDX12
			11001b: TS35
PE3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC1B	00001b: MTIOC4B
			00010b: MTIOC1B
		00011b: MTIOC0A	
			00111b: POE8#
			01001b: CLKOUT
		01100b: CTS12#/RTS12#/SS12#	01100b: CTS12#/RTS12#/SS12#
		01101b: RSPCKA	
			11001b: TS34

Register	Bit	RX110 (n = 0 to 7)	RX140 (n = 0 to 5)
PE4PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4D
		00010b: MTIOC1A	00010b: MTIOC1A
			00011b: MTIOC4A
			01001b: CLKOUT
		01101b: MOSIA	
			11001b: TS33
PE5PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4C
		00010b: MTIOC2B	00010b: MTIOC2B
			10000b: CMPOB0
PE6PFS		PE6 pin function control register	_
PE7PFS	_	PE7 pin function control register	_
PEnPFS	ISEL	Interrupt input function select bit	Interrupt input function select bit
		0: Not used as IRQn input pin	0: Not used as IRQn input pin
		1: Used as IRQn input pin	1: Used as IRQn input pin
		PE0: IRQ0 (64/48/40/36-pin)	
		PE1: IRQ1 (64/48/40/36-pin)	
		PE2: IRQ7 (64/48/40/36-pin)	PE2: IRQ7 (80/64/48/32-pin)
		PE3: IRQ3 (64/48/40/36-pin)	
		PE4: IRQ4 (64/48/40/36-pin)	
		PE5: IRQ5 (64-pin)	PE5: IRQ5 (80/64-pin)
		PE6: IRQ6 (64-pin)	
		PE7: IRQ7 (64/48-pin)	
	ASEL	Analog function select bit	Analog function select bit
		0: Used as other than as analog pin	0: Used as other than as analog pin
		1: Used as analog pin	1: Used as analog pin
		PE0: AN008 (64/48/40/36-pin)	PE0: AN016 (80/64-pin)
		PE1: AN009 (64/48/40/36-pin)	PE1: AN017, CMPB0
			(80/64/48/32-pin)
		PE2: AN010 (64/48/40/36-pin)	PE2: AN018, CVREFB0
			(80/64/48/32-pin)
		PE3: AN011 (64/48/40/36-pin)	PE3: AN019 (80/64/48/32-pin)
		PE4: AN012 (64/48/40/36-pin)	PE4: AN020, CMPA2
			(80/64/48/32-pin)
		PE5: AN013 (64-pin)	PE5: AN021 (80/64-pin)
		PE6: AN014 (64-pin)	
		PE7: AN015 (64/48-pin)	

Table 2.40 Comparison of PHn Pin Function Control Register (PHnPFS)

Register	Bit	RX110 (n = 0 to 3)	RX140 (n = 0 to 3)
PH0PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC1B	00001b: MTIOC3B
		00111b: CACREF	00111b: CACREF
			11001b: TS10
PH1PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC3D
			00101b: TMO0
			11001b: TS9
PH2PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
			00001b: MTIOC4C
			00101b: TMRI0
			11001b: TS8
PH3PFS	PSEL[4:0]	Pin function select bits	Pin function select bits
		00000b: Hi-Z	00000b: Hi-Z
		00001b: MTIOC1A	00001b: MTIOC4D
			00101b: TMCI0
			11001b: TS7

Table 2.41 Comparison of PJn Pin Function Control Register (PJnPFS)

Register	Bit	RX110 (n = 6, 7)	RX140 (n = 1, 6, 7)
PJ1PFS	_	_	PJ1 pin function control register
PJ6PFS	ASEL	Analog function select bit	Analog function select bit
		0: The AVCC0 pin is selected as the reference power supply pin for the high-potential side.	0: Used as other than as analog pin
		1: The VREFH0 pin is selected as the reference power supply pin for the high-potential side.	1: Used as analog pin
			PJ6: VREFH0 (80/64/48-pin)
PJ7PFS	ASEL	Analog function select bit	Analog function select bit
		0: The AVSS0 pin is selected as the reference power supply ground pin for the low-potential side.	0: Used as other than as analog pin
		1: The VREFL0 pin is selected as the reference power supply ground pin for the low-potential side.	1: Used as analog pin
			PJ7: VREFL0 (80/64/48-pin)

2.15 Multi-Function Timer Pulse Unit 2

Table 2.42 is a comparative overview of multi-function timer pulse unit 2, and Table 2.43 is a comparison of multi-function timer pulse unit 2 registers.

Table 2.42 Comparative Overview of Multi-Function Timer Pulse Unit 2

Item	RX110 (MTU2b)	RX140 (MTU2a)
Pulse input/output	Max. 8 lines	Max. 16 lines
Pulse input	3 lines	3 lines
Count clocks	Eight or Seven clocks for each channel (four clocks for MTU5)	Eight or Seven clocks for each channel (four clocks for MTU5)
Available operations	 [MTU0 to MTU2] Waveform output at compare match Input capture function (noise filter setting function) Counter clear operation Simultaneous writing to multiple timer counters (TCNT) Simultaneous clearing by compare match or input capture Simultaneous register input/output by synchronous counter operation Up to 8-phase PWM output in combination with synchronous operation 	 [MTU0 to MTU4] Waveform output at compare match Input capture function (noise filter setting function) Counter clear operation Simultaneous writing to multiple timer counters (TCNT) Simultaneous clearing by compare match or input capture Simultaneous register input/output by synchronous counter operation Up to 12-phase PWM output in combination with synchronous operation
	[MTU0] • Ability to specify buffer operation	 [MMTU0, MTU3, MTU4] Ability to specify buffer operation Ability to specify AC synchronous motor (brushless DC motor) drive mode using complementary PWM or reset-synchronized PWM and to select between two types of waveform output (chopping or level)
	 [MTU1, MTU2] Independent specification of phase counting mode Cascade connection operation 	 [MTU1, MTU2] Independent specification of phase counting mode Cascade connection operation [MTU3, MTU4] Ability to output three positive and three negative phases (total six phases) using continuous operation of complementary PWM or resetsynchronized PWM
	[MTU5]	[MTU5]Counter function for dead time compensation
	Input capture function (noise filter setting)	Input capture function (noise filter setting)
	Counter clear operation	Counter clear operation

Item	RX110 (MTU2b)	RX140 (MTU2a)
Complementary PWM mode		 Interrupts at peaks or troughs of counter A/D converter conversion start trigger skipping function
Interrupt sources	18 sources	28 sources
Buffer operation	Automatic transfer of register data	Automatic transfer of register data
Trigger generation	Ability to generate A/D converter start trigger	Ability to generate A/D converter start trigger
Low power consumption function	Ability to specify module stop state	Ability to transition to module stop state

Table 2.43 Comparison of Multi-Function Timer Pulse Unit 2 Registers

Register	Bit	RX110 (MTU2b)	RX140 (MTU2a)
TMDR	MD[3:0]	Mode select bits	Mode select bits
		b3 b0	b3 b0
		0 0 0 0: Normal mode	0 0 0 0: Normal mode
		0 0 0 1: Setting prohibited	0 0 0 1: Setting prohibited
		0 0 1 0: PWM mode 1	0 0 1 0: PWM mode 1
		0 0 1 1: PWM mode 2	0 0 1 1: PWM mode 2
		0 1 0 0: Phase counting mode 1	0 1 0 0: Phase counting mode 1
		0 1 0 1: Phase counting mode 2	0 1 0 1: Phase counting mode 2
		0 1 1 0: Phase counting mode 3	0 1 1 0: Phase counting mode 3
		0 1 1 1: Phase counting mode 4	0 1 1 1: Phase counting mode 4
		1 x x x: Setting prohibited	1 0 0 0: Reset-synchronized PWM mode
			1 0 0 1: Setting prohibited
			1 0 1 x: Setting prohibited
			1 1 0 0: Setting prohibited
			1 1 0 1: Complementary PWM mode 1 (transfer at peak)
			1 1 1 0: Complementary PWM mode 2 (transfer at trough)
			1 1 1 1: Complementary PWM mode 3 (transfer at peak and trough)

Register	Bit	RX110 (MTU2b)	RX140 (MTU2a)
TIORU	IOC[4:0]	I/O control C bits	I/O control C bits
TIORV]		
TIORW		b4 b0	b4 b0
		0 0 0 0 0: Compare match	0 0 0 0 0: No function
		0 0 0 0 1: Setting prohibited	0 0 0 0 1: Setting prohibited
		0 0 0 1 x: Setting prohibited	0 0 0 1 x: Setting prohibited
		0 0 1 x x: Setting prohibited	0 0 1 x x: Setting prohibited
		0 1 x x x: Setting prohibited	0 1 x x x: Setting prohibited
		1 0 0 0 0: Setting prohibited	1 0 0 0 0: Setting prohibited
		1 0 0 0 1: Input capture at rising edge	1 0 0 0 1: Input capture at rising edge
		1 0 0 1 0: Input capture at falling edge	1 0 0 1 0: Input capture at falling edge
		1 0 0 1 1: Input capture at both edges	1 0 0 1 1: Input capture at both edges
		1 0 1 x x: Setting prohibited	1 0 1 x x: Setting prohibited
		1 1 0 0 0: Setting prohibited	1 1 0 0 0: Setting prohibited
		1 1 0 0 1: Measurement of low pulse	1 1 0 0 1: Measurement of low pulse
		width of external input signal	width of external input signal
			Capture at trough in
		4.4.0.4.0. Management of law pulsa	complementary PWM mode
		1 1 0 1 0: Measurement of low pulse width of external input signal	1 1 0 1 0: Measurement of low pulse width of external input signal
		width of external input signal	Capture at peak in
			complementary PWM mode
		1 1 0 1 1: Measurement of low pulse	1 1 0 1 1: Measurement of low pulse
		width of external input signal	width of external input signal
		width of external input signal	Capture at peak and trough
			in complementary PWM
			mode
		1 1 1 0 0: Setting prohibited	1 1 1 0 0: Setting prohibited
		1 1 1 0 1: Measurement of high pulse	1 1 1 0 1: Measurement of high pulse
		width of external input signal	width of external input signal
			Capture at trough in
			complementary PWM mode
		1 1 1 1 0: Measurement of high pulse	1 1 1 1 0: Measurement of high pulse
		width of external input signal	width of external input signal
			Capture at peak in
			complementary PWM mode
		1 1 1 1 1: Measurement of high pulse	1 1 1 1 1: Measurement of high pulse
		width of external input signal	width of external input signal
			Capture at peak and trough
			in complementary PWM
TIED	TTOFO		mode
TIER	TTGE2	_	A/D converter start request enable 2
TADCR			bit Timer A/D converter start request
TADCK	—	_	Timer A/D converter start request
TADCODA			control register
TADCORR	—	_	Timer A/D converter start request cycle
TADCORB			set registers A and B
TADCOBRA			Timer A/D converter start request cycle
TADCOBRB	CTC2		set buffer registers A and B
TSTR	CTS3	-	Counter start 3 bit
TOVD	CTS4	-	Counter start 4 bit
TSYR	SYNC3	_	Timer synchronous operation 3 bit
	SYNC4	_	Timer synchronous operation 4 bit
TRWER	<u> —</u>	<u> </u>	Timer read/write enable register

Register	Bit	RX110 (MTU2b)	RX140 (MTU2a)
TOER	_	_	Timer output master enable register
TOCR1	_	_	Timer output control register 1
TOCR2	_	_	Timer output control register 2
TOLBR	_	_	Timer output level buffer register
TGCR	_	_	Timer gate control register
TCNTS	_	_	Timer subcounter
TDDR	_	_	Timer dead time data register
TCDR	_	_	Timer cycle data register
TCBR	_	_	Timer cycle buffer register
TITCR	_	_	Timer interrupt skipping set register
TITCNT	_	_	Timer interrupt skipping counter
TBTER	_	_	Timer buffer transfer set register
TDER	_	_	Timer dead time enable register
TWCR	_	_	Timer waveform control register

2.16 Compare Match Timer

Table 2.44 is a comparative overview of the compare match timers.

Table 2.44 Comparative Overview of Compare Match Timers

Item	RX110	RX140
Count clocks	Four frequency-divided clocks: One clock from among PCLK/8, PCLK/32, PCLK/128, and PCLK/512 can be selected individually for each channel.	Four frequency-divided clocks: One clock from among PCLK/8, PCLK/32, PCLK/128, and PCLK/512 can be selected individually for each channel.
Interrupt	A compare match interrupt can be requested individually for each channel.	A compare match interrupt can be requested for each channel.
Event link function (output)	_	Event signal output at CMT1 compare match
Event link function (input)		 Support for linked operation of specified module Support for CMT1 counter start, event counter, and count restart
Low power consumption function	Ability to specify module stop state	Ability to specify module stop state

2.17 Realtime Clock

Table 2.45 is a comparison of realtime clock registers.

Table 2.45 Comparison of Realtime Clock Registers

Register	Bit	RX110 (RTCA)	RX140 (RTCc)
RCR3		RTC control register 3	_

2.18 Serial Communications Interface

Table 2.46 is a comparative overview of the serial communications interfaces, and Table 2.47 is a comparison of serial communications interface channel specifications, and Table 2.48 is a comparison of serial communications interface registers.

Table 2.46 Comparative Overview of Serial Communications Interfaces

Item		RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Number of channels		SCIe: 2 channelsSCIf: 1 channel	SClg: 3 channelsSClk: 2 channelsSClh: 1 channel
Serial communi	cations modes	 Asynchronous Clock synchronous Smart card interface Simple I²C bus Simple SPI bus 	 Asynchronous Clock synchronous Smart card interface Simple I²C bus Simple SPI bus
Transfer speed		Bit rate specifiable by on-chip baud rate generator.	Bit rate specifiable by on-chip baud rate generator.
Full-duplex com	nmunication	 Transmitter: Continuous transmission possible using double-buffer structure. Receiver: Continuous reception possible using double-buffer structure. 	 Transmitter: Continuous transmission possible using double-buffer structure. Receiver: Continuous reception possible using double-buffer structure.
Data transfer		Selectable as LSB first or MSB first transfer.	Selectable as LSB first or MSB first transfer.
I/O signal level	inversion		The levels of input and output signals can be inverted independently (SCI1 and SCI5).
Interrupt source	es	Transmit end, transmit data empty, receive data full, and receive error, completion of generation of a start condition, restart condition, or stop condition (for simple I ² C mode)	Transmit end, transmit data empty, receive data full, receive error, and data match (SCI1 and SCI5), completion of generation of a start condition, restart condition, or stop condition (for simple I ² C mode)
Low power cons	sumption function	Individual channels can be transitioned to the module stop state.	Individual channels can be transitioned to the module stop state.
Asynchronous mode	Data length Transmission stop bits	7 or 8 bits 1 or 2 bits	7, 8, or 9 bits 1 or 2 bits
	Parity	Even parity, odd parity, or no parity	Even parity, odd parity, or no parity
	Receive error detection function	Parity, overrun, and framing errors	Parity, overrun, and framing errors
	Hardware flow control	CTSn# and RTSn# pins can be used in controlling transmission/reception.	CTSn# and RTSn# pins can be used in controlling transmission/reception.

Item		RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Asynchronous mode	Data match detection		Compares receive data and comparison data, and generates interrupt when they are matched (SCI1 and SCI5)
	Start-bit detection	Low level or falling edge is selectable.	Low level or falling edge is selectable.
	Receive data sampling timing adjustment		The receive data sampling point can be shifted from the center of the data forward or backward to a base point (SCI1 and SCI5).
	Transmit signal change timing adjustment	_	Either the falling or rising edge of the transmit data can be delayed (SCI1 and SCI5).
	Break detection	When a framing error occurs, a break can be detected by reading the RXDn pin level directly.	When a framing error occurs, a break can be detected by reading the RXDn pin level directly or by reading the SPTR.RXDMON flag (SCI1 or SCI5).
	Clock source	 An internal or external clock can be selected. Transfer rate clock input from the TMR can be used (SCI1, SCI5, and SCI12). 	 An internal or external clock can be selected. Transfer rate clock input from the TMR can be used (SCI5, SCI6, and SCI12).
	Double-speed mode	_	Baud rate generator double-speed mode is selectable.
	Multi-processor communications function	Serial communication among multiple processors	Serial communication among multiple processors
	Noise cancellation	The signal paths from input on the RXDn pins incorporate digital noise filters.	The signal paths from input on the RXDn pins incorporate digital noise filters.
Clock	Data length	8 bits	8 bits
synchronous mode	Receive error detection	Overrun error	Overrun error
	Hardware flow control	CTSn# and RTSn# pins can be used in controlling transmission/ reception.	CTSn# and RTSn# pins can be used in controlling transmission/ reception.
Smart card interface mode	Error processing	 An error signal can be automatically transmitted when detecting a parity error during reception Data can be automatically retransmitted when receiving an error signal during transmission 	 An error signal can be automatically transmitted when detecting a parity error during reception Data can be automatically retransmitted when receiving an error signal during transmission
	Data type	Both direct convention and inverse convention are supported.	Both direct convention and inverse convention are supported.
Simple I ² C mode	Communication format	I ² C bus format	I ² C bus format
	Operating mode	Master (single-master operation only)	Master (single-master operation only)
	Transfer rate	Fast mode is supported.	Fast mode is supported.

Item		RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Simple I ² C mode	Noise cancellation	The signal paths from input on the SSCLn and SSDAn pins incorporate digital noise filters, and the interval for noise cancellation is adjustable.	The signal paths from input on the SSCLn and SSDAn pins incorporate digital noise filters, and the interval for noise cancellation is adjustable.
Simple SPI	Data length	8 bits	8 bits
mode	Detection of errors	Overrun error	Overrun error
	SS input pin function	Applying the high level to the SSn# pin can cause the output pins to enter the high-impedance state.	Applying the high level to the SSn# pin can cause the output pins to enter the high-impedance state.
	Clock settings	Four kinds of settings for clock phase and clock polarity are selectable.	Four kinds of settings for clock phase and clock polarity are selectable.
Extended serial mode (supported by SCI12 only)	Start frame transmission	 Break field low width output and generation of interrupt on completion Detection of bus collision and generation of interrupt on detection 	 Break field low width output and generation of interrupt on completion Detection of bus collision and generation of interrupt on detection
	Start frame reception	 Detection of break field low width and generation of interrupt on detection Data comparison of control fields 0 and 1 and generation of interrupt when they match Ability to specify two kinds of data for comparison (primary and secondary) in control field 1 Ability to specify priority interrupt bit in control field 1 Support for start frames that do not include a break field Support for start frames that do not include a control field 0 Function for measuring bit rates Ability to select polarity or TXDX12 and RXDX12 signals 	 Detection of break field low width and generation of interrupt on detection Data comparison of control fields 0 and 1 and generation of interrupt when they match Ability to specify two kinds of data for comparison (primary and secondary) in control field 1 Ability to specify priority interrupt bit in control field 1 Support for start frames that do not include a break field Support for start frames that do not include a control field 0 Function for measuring bit rates Ability to select polarity or TXDX12 and RXDX12 signals
	Timer function	 Ability to specify digital filtering of RXDX12 signal Half-duplex operation employing RXDX12 and TXDX12 signals multiplexed on the same pin Ability to select receive data sampling timing of RXDX12 pin Usable as reloading timer 	 Ability to specify digital filtering of RXDX12 signal Half-duplex operation employing RXDX12 and TXDX12 signals multiplexed on the same pin Ability to select receive data sampling timing of RXDX12 pin Usable as reloading timer
Bit rate modulat			Correction of outputs from the
			on-chip baud rate generator can reduce errors.

Item	RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Event link function (supported by SCI5 only)		 Error (receive error or error signal detection) event output Receive data full event output Transmit data empty event
		output Transmit end event output

Table 2.47 Comparison of Serial Communications Interface Channel Specifications

Item	RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
Synchronous mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Clock synchronous mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Smart card interface mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Simple I ² C mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Simple SPI mode	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12
Data match detection	_	SCI1, SCI5
Extended serial mode	SCI12	SCI12
MTU clock input (RX110)	SCI1, SCI5, SCI12	SCI5, SCI6, SCI12
TMR clock input (RX140)		
Event link function	_	SCI5
Peripheral module clock	PCLKB:	PCLKB:
	SCI1, SCI5, SCI12	SCI1, SCI5, SCI6, SCI8, SCI9, SCI12

Table 2.48 Comparison of Serial Communications Interface Registers

Register	Bit	RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
RDRH RDRL RDRHL	_		Receive data registers H, L, and HL
TDRH TDRL TDRHL	_	_	Transmit data registers H, L, and HL
SMR	CHR	Character length bit	Character length bit
		(Valid only in asynchronous mode)	(Valid only in asynchronous mode) Selections are made in combination with the SCMR.CHR1 bit. CHR1 CHR
		Selects 8 bits as the data length for transmission and reception Selects 7 bits as the data length for transmission and reception	 0 0: Selects 9 bits as the data length for transmission and reception 0 1: Selects 9 bits as the data length for transmission and reception 1 0: Selects 8 bits as the data length for transmission and reception (initial value) 1 1: Selects 7 bits as the data length for transmission and reception

Register	Bit	RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
SCR	CKE[1:0]	Clock enable bits	Clock enable bits
(when			
SCMR.SMIF = 0)		(Asynchronous mode) b1 b0	(Asynchronous mode) b1 b0
,		0 0: On-chip baud rate generator The SCKn pin can be used as an I/O port by means of an I/O port setting.	0 0: On-chip baud rate generator The SCKn pin is in the high- impedance state.
		 0 1: On-chip baud rate generator A clock with the same frequency as the bit rate is output on the SCKn pin. 1 x: External clock or MTU clock When using an external clock, input a clock with a frequency 16 times the bit rate on the SCKn pin. When the SEMR.ABCS bit is set to 1, input a clock with a frequency eight times the bit rate. The MTU clock can be used. When using the MTU clock, the SCKn pin can be used as an I/O port by means of an I/O port setting. 	 0 1: On-chip baud rate generator A clock with the same frequency as the bit rate is output on the SCKn pin. 1 x: External clock or TMR clock*1 • When using an external clock, input a clock with a frequency 16 times the bit rate on the SCKn pin. When the SEMR.ABCS bit is set to 1, input a clock with a frequency eight times the bit rate. • When using the TMR clock, the SCKn pin is in the high- impedance state.
		(Clock synchronous mode) b1 b0 0 x: Internal clock: The SCKn pin functions as the clock output pin. 1 x: External clock: The SCKn pin functions as the clock input pin.	(Clock synchronous mode) b1 b0 0 x: Internal clock: The SCKn pin functions as the clock output pin. 1 x: External clock: The SCKn pin functions as the clock input pin.
	MPIE	Multi-processor interrupt enable bit (Valid in asynchronous mode when	Multi-processor interrupt enable bit (Valid in asynchronous mode when
		(Valid in asynchronous mode when SMR.MP bit = 1) 0: Normal receive operation 1: When data is received while the multi-processor bit is set to 0, the data is skipped, and setting (to 1) of status flags ORER, and FER in SSR is disabled. When data is received while the multi-processor bit is set to 1, the MPIE bit is automatically cleared to 0, and normal receive operation resumes.	SMR.MP bit = 1) 0: Normal receive operation 1: When data is received while the multi-processor bit is set to 0, the data is skipped, and setting (to 1) of status flags RDRF, ORER, and FER in SSR is disabled. When data is received while the multi-processor bit is set to 1, the MPIE bit is automatically cleared to 0, and normal receive operation resumes.

Register	Bit	RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
SCR	CKE[1:0]	Clock enable bits	Clock enable bits
(when			
SCMR.SMIF		(When the SMR.GM bit = 0)	(When the SMR.GM bit = 0)
= 1)		b1 b0	b1 b0
		0 0: Output disabled	0 0: Output disabled
		(The SCKn pin can be used as	The SCKn pin is in the high-
		an I/O port by means of an I/O	impedance state.
		port setting.)	· ·
		0 1: Clock output	0 1: Clock output
		1 x: (Setting prohibited)	1 x: Setting prohibited
		(When the SMR.GM bit = 1)	(When the SMR.GM bit = 1)
		b1 b0	b1 b0
		0 0: Low-level output fixed	0 0: Low-level output fixed
		x 1: Clock output	x 1: Clock output
		1 0: High-level output fixed	1 0: High-level output fixed
SCMR	CHR1		Character length bit
MDDR		_	Modulation duty register
SEMR	ACS0	Asynchronous mode clock source	Asynchronous mode clock source
02	7.000	select bit	select bit
		(Valid only in asynchronous mode)	(Valid only in asynchronous mode)
		0: External clock	0: External clock
		1: Logical AND of two compare	1: Logical AND of two compare
		matches output from MTU	matches output from TMR (valid
		,	for SCI5, SCI6, and SCI12 only)
			The compare match outputs that
			can be used differ according to the
			SCI channel.
	ITE	_	Immediate transmission enable bit
	BRME	_	Bit rate modulation enable bit
	ABCSE		Asynchronous basic clock select
			extended bit
	BGDM	_	Baud rate generator double-speed
			mode select bit
SPMR	MSS	Master slave select bit	Master slave select bit
		0: TXDn pin: transmission,	0: SMOSIn pin: transmission,
		RXDn pin: reception	SMISOn pin: reception
		(master mode)	(master mode)
		1: TXDn pin: reception,	1: SMOSIn pin: reception,
		RXDn pin: transmission (slave mode)	SMISOn pin: transmission (slave mode)
CDR		(Slave Hode)	Comparison data register
DCCR			Data comparison control register
SPTR			Serial port register
		_	•
TMGR		_	Transmit/receive timing select register
			register

Register	Bit	RX110 (SCIe, SCIf)	RX140 (SCIg, SCIk, SCIh)
CR2	BCCS[1:0]	Bus collision detection clock select bits	Bus collision detection clock select bits (When the SEMR.BGDM bit is
		b5 b4	cleared to 0 or the SEMR.BGDM bit is set to 1 and the SMR.CKS[1:0] bits are set to a value other than 00b) b5 b4
		0 0: SCI base clock	0 0: Base clock
		0 1: SCI base clock frequency divided by 2	0 1: Base clock frequency divided by 2
		1 0: SCI base clock frequency divided by 4	1 0: Base clock frequency divided by 4
		1 1: Setting prohibited	1 1: Setting prohibited
			(When the SEMR.BGDM bit is set to 1 and the SMR.CKS[1:0] bits are set to 00b)
			b5 b4
			0 0: Base clock frequency divided by 2
			0 1: Base clock frequency divided by 4
			1 0: Setting prohibited
			1 1: Setting prohibited

Note: 1. Selectable on SCI5, SCI6, and SCI12 only.

2.19 I²C bus Interface

Table 2.49 is a comparative overview of the I^2C bus interfaces, and Table 2.50 is a comparison of I^2C bus interface registers.

Table 2.49 Comparative Overview of I²C Bus Interfaces

Item RX110 (RIIC) RX140 (RIICa)		RX140 (RIICa)
Communication format	 I²C bus format or SMBus format Selectable between master mode or slave mode. Automatic securing of the various setup times, hold times, and bus-free times for the transfer rate 	 I²C bus format or SMBus format Selectable between master mode or slave mode. Automatic securing of the various setup times, hold times, and bus-free times for the transfer rate
Transfer speed	Fast mode is supported (up to 400 kbps).	Fast mode is supported (up to 400 kbps).
Serial clock (SCL)	For master operation, the duty cycle of the SCL clock is selectable in the range from 4% to 96%.	For master operation, the duty cycle of the SCL clock is selectable in the range from 4% to 96%.
Issuing and detection conditions	 Start, restart, and stop conditions are generated automatically. Start conditions (including restart conditions) and stop conditions are detectable. 	 Start, restart, and stop conditions are generated automatically. Start conditions (including restart conditions) and stop conditions are detectable.
Slave addresses	 Up to three different slave addresses can be set. T-bit and 10-bit address formats are supported (along with the use of both at once). General call addresses, device ID addresses, and SMBus host addresses are detectable. Up to three different slave can be set. 7-bit and 10-bit address formats are supported (along with the at once). General call addresses, and SMBus haddresses are detectable. 	
Acknowledgement	 For transmission, the acknowledge bit is loaded automatically. Transfer of the next data for transmission can be suspended automatically on reception of a not-acknowledge bit. For reception, the acknowledge bit is transmitted automatically. If a wait between the eighth and ninth clock cycles has been selected, software control of the value in the acknowledge field in response to the received value is possible. 	 For transmission, the acknowledge bit is loaded automatically. Transfer of the next data for transmission can be suspended automatically on reception of a not-acknowledge bit. For reception, the acknowledge bit is transmitted automatically. If a wait between the eighth and ninth clock cycles has been selected, software control of the value in the acknowledge field in response to the received value is possible.
Wait function	For reception, the following wait periods can be obtained by holding the SCL clock at the low level: Wait between the eighth and ninth clock cycles Wait between the ninth and first clock cycles	For reception, the following wait periods can be obtained by holding the SCL line at the low level: Wait between the eighth and ninth clock cycles Wait between the ninth and first clock cycles
SDA output delay function	Timing of the output of transmitted data, including the acknowledge bit, can be delayed.	Timing of the output of transmitted data, including the acknowledge bit, can be delayed.

Item	RX110 (RIIC)	RX140 (RIICa)	
Arbitration	 Multi-master support Operation to synchronize the SCL clock in cases of conflict with the SCL clock from another master is possible. When issuing a start condition, loss of arbitration is detected by testing for non-matching of the signals for the SDA line. In master operation, loss of arbitration is detected by testing for non-matching of transmit data. Loss of arbitration due to detection of a start condition while the bus is busy is detectable (to prevent the issuing of double start conditions). Loss of arbitration in transfer of a not-acknowledge bit due to the signals for the SDA line not matching is detectable. Loss of arbitration due to non-matching of data is detectable in slave transmission. 	 Multi-master support Operation to synchronize the SCL clock in cases of conflict with the SCL clock from another master is possible. When issuing a start condition, loss of arbitration is detected by testing for non-matching of the signals for the SDA line. In master operation, loss of arbitration is detected by testing for non-matching of transmit data. Loss of arbitration due to detection of a start condition while the bus is busy is detectable (to prevent the issuing of double start conditions). Loss of arbitration in transfer of a not-acknowledge bit due to the signals for the SDA line not matching is detectable. Loss of arbitration due to non-matching of data is detectable in slave 	
Timeout detection function	The internal timeout function is capable of detecting long-interval stop of the SCL clock.	transmission. The internal timeout function is capable of detecting long-interval stop of the SCL clock.	
Noise canceler	The interface incorporates digital noise filters for both the SCL and SDA inputs, and the bandwidth for noise cancellation by the filters is adjustable by software.	The interface incorporates digital noise filters for both the SCL and SDA inputs, and the bandwidth for noise cancellation by the filters is adjustable by software.	
Interrupt sources	Four sources: Error in transfer or occurrence of events (detection of arbitration, NACK, time out, a start condition including a restart condition, or a stop condition) Receive data full (including matching with a slave address) Transmit data empty (including matching with a slave address) Transmission complete	Four sources: Error in transfer or occurrence of events (detection of arbitration loss, NACK, timeout, a start condition including a restart condition, or a stop condition) Receive data full (including matching with a slave address) Transmit data empty (including matching with a slave address) Transmit end	
Low power consumption function	Ability to transition to module stop state	Ability to transition to module stop state	
RIIC operating modes	Four modes: Master transmit mode Master receive mode Slave transmit mode Slave receive mode	Four modes: Master transmit mode Master receive mode Slave transmit mode Slave receive mode	

Item	RX110 (RIIC)	RX140 (RIICa)
Event link function	_	Four sources (RIIC0):
(output)		Error in transfer or occurrence of events Detection of arbitration loss, NACK, timeout, a start condition including a restart condition, or a stop condition
		 Receive data full (including matching with a slave address) Transmit data empty (including matching with a slave address)
		Transmit end

Table 2.50 Comparison of I²C Bus Interface Registers

Register	Bit	RX110 (RIIC)	RX140 (RIICa)
ICMR2	TMWE	Timeout internal counter write enable bit	_
TMOCNTL TMOCNTU	_	Timeout internal counter	_

2.20 Serial Peripheral Interface

Table 2.51 is a comparative overview of serial peripheral interfaces, and Table 2.52 is a comparison of serial peripheral interface registers.

Table 2.51 Comparative Overview of Serial Peripheral Interfaces

Item	RX110 (RSPI)	RX140 (RSPIc)		
Number of channels	1 channel	1 channel		
RSPI transfer functions	Use of MOSI (master out/slave in), MISO (master in/slave out), SSL (slave select), and RSPCK (RSPI clock) signals allows serial communications through SPI operation (4-wire method) or clock synchronous operation (3-wire method). Transmit-only operation is available. Communication mode: Full-duplex or transmit-only can be selected.	Use of MOSI (master out/slave in), MISO (master in/slave out), SSL (slave select), and RSPCK (RSPI clock) signals allows serial communications through SPI operation (4-wire method) or clock synchronous operation (3-wire method). Communication mode: Full-duplex or transmit-only can be selected.		
	Switching of the polarity of RSPCK	Switching of the polarity of RSPCK		
	Switching of the phase of RSPCK	Switching of the phase of RSPCK		
Data format	 MSB first/LSB first selectable Transfer bit length is selectable as 8, 9, 10, 11, 12, 13, 14, 15, 16, 20, 24, or 32 bits. 128-bit transmit/receive buffers 	 MSB first/LSB first selectable Transfer bit length is selectable as 8, 9, 10, 11, 12, 13, 14, 15, 16, 20, 24, or 32 bits. 128-bit transmit/receive buffers 		
	Up to four frames can be transferred in one round of transmission/reception (each frame consisting of up to 32 bits).	 Up to four frames can be transferred in one round of transmission/reception (each frame consisting of up to 32 bits). Byte swapping of transmit and receive data is selectable 		
Bit rate	 In master mode, the on-chip baud rate generator generates RSPCK by frequency-dividing PCLK (the division ratio ranges from divided by 2 to divided by 4096). In slave mode, the minimum PCLK clock divided by 8 can be input as RSPCK (the maximum frequency of RSPCK is that of PCLK divided by 8). Width at high level: 4 cycles of PCLK Width at low level: 4 cycles of PCLK 	 In master mode, the on-chip baud rate generator generates RSPCK by frequency-dividing PCLK (the division ratio ranges from divided by 2 to divided by 4096). In slave mode, the minimum PCLK clock divided by 4 can be input as RSPCK (the maximum frequency of RSPCK is that of PCLK divided by 4). Width at high level: 2 cycles of PCLK Width at low level: 2 cycles of PCLK 		
Buffer configuration	 Double buffer configuration for the transmit/receive buffers 128 bits for the transmit/receive buffers 	 Double buffer configuration for the transmit/receive buffers 128 bits for the transmit/receive buffers 		
Error detection	 Mode fault error detection Overrun error detection Parity error detection 	 Mode fault error detection Overrun error detection Parity error detection Underrun error detection 		

Item	RX110 (RSPI)	RX140 (RSPIc)
SSL control function	Four SSL pins (SSLA0 to SSLA3) for	Four SSL pins (SSLA0 to SSLA3) for
	each channel	each channel
	In single-master mode, SSLA0 to	 In single-master mode, SSLA0 to
	SSLA3 pins are output.	SSLA3 pins are output.
	In multi-master mode: SCI A0 pin for input, and SCI A1 to	In multi-master mode: OCI A0 min for input, and CCI A1 to
	SSLA0 pin for input, and SSLA1 to SSLA3 pins for either output or	SSLA0 pin for input, and SSLA1 to SSLA3 pins for either output or
	unused.	unused.
	In slave mode:	In slave mode:
	SSLA0 pin for input, and SSLA1 to SSLA3 pins for unused.	SSLA0 pin for input, and SSLA1 to SSLA3 pins for unused.
	Controllable delay from SSL output	Controllable delay from SSL output
	assertion to RSPCK operation (RSPCK delay)	assertion to RSPCK operation (RSPCK delay)
	 Range: 1 to 8 RSPCK cycles (set in RSPCK-cycle units) 	 Range: 1 to 8 RSPCK cycles (set in RSPCK-cycle units)
	Controllable delay from RSPCK stop	Controllable delay from RSPCK stop
	to SSL output negation (SSL negation delay)	to SSL output negation (SSL negation delay)
	 Range: 1 to 8 RSPCK cycles (set in RSPCK-cycle units) 	 Range: 1 to 8 RSPCK cycles (set in RSPCK-cycle units)
	Controllable wait for next-access	Controllable wait for next-access
	SSL output assertion (next-access delay)	SSL output assertion (next-access delay)
	— Range:1 to 8 RSPCK cycles (set	— Range:1 to 8 RSPCK cycles (set
	in RSPCK-cycle units)	in RSPCK-cycle units)
Control in master	Function for changing SSL polarityA transfer of up to eight commands	 Function for changing SSL polarity A transfer of up to eight commands
transfer	can be executed sequentially in	can be executed sequentially in
	looped execution.	looped execution.
	For each command, the following	For each command, the following
	can be set:	can be set:
	SSL signal value, bit rate, RSPCK polarity/phase, transfer data length,	SSL signal value, bit rate, RSPCK polarity/phase, transfer data length,
	MSB/LSB first, burst, RSPCK delay,	MSB/LSB first, burst, RSPCK delay,
	SSL negation delay, and next-access delay	SSL negation delay, and next-access delay
	A transfer can be initiated by writing to the transmit buffer.	A transfer can be initiated by writing to the transmit buffer.
	MOSI signal value specifiable in SSL	MOSI signal value specifiable in SSL
	negation	negation
		RSPCK auto-stop function
Interrupt sources	Receive buffer full interrupt	Receive buffer full interrupt
	Transmit buffer empty interrupt	Transmit buffer empty interrupt
	RSPI error interrupt (mode fault,	Error interrupt (mode fault, overrun,
	overrun, or parity error)	underrun, or parity error)
Other functions	RSPI idle interrupt (RSPI idle)Function for switching between	Idle interruptFunction for switching between
Other fulletions	CMOS output and open-drain output	CMOS output and open-drain output
	Function for initializing the RSPI	Function for initializing the RSPI
	Loopback mode	Loopback mode
Low power	Ability to specify module stop state.	Ability to specify module stop state.
consumption		
function		

Table 2.52 Comparison of Serial Peripheral Interface Registers

Register	Bit	RX110 (RSPIa)	RX140 (RSPIc)
SPSR	MODF	Mode fault error flag	Mode fault error flag
		0: No mode fault error occurs	Neither a mode fault error nor an underrun error occurs
		1: A mode fault error occurs	A mode fault error or an underrun error occurs
	UDRF	_	Underrun error flag
SPDR	_	RSPI data register	RSPI data register
		Accessible size	Accessible size
		Longwords access (SPDCR.SPLW = 1)	 Longwords access (SPDCR.SPLW = 1, SPBYTE = 0)
		Words access (SPDCR.SPLW = 0)	• Words access (SPDCR.SPLW = 0, SPBYTE = 0)
			Bytes access (SPDCR.SPBYT = 1)
SPDCR	SPBYT	_	RSPI byte access specification bit
SPCR2	SPPE	Parity enable bit	Parity enable bit
		A parity bit is not added to transmit data, and no parity checking of receive data is performed.	A parity bit is not added to transmit data, and no parity checking of receive data is performed.
		1: A parity bit is added to transmit data, and parity checking of receive data is performed (when SPCR.TXMD = 0).	1: A parity bit is added to transmit data, and parity checking of receive data is performed.
		A parity bit is added to transmit data, but no parity checking of receive data is performed (when SPCR.TXMD = 1).	
	SCKASE		RSPCK auto-stop function enable bit
SPDCR2		_	RSPI data control register 2

2.21 12-Bit A/D Converter

Table 2.53 is a comparative overview of the 12-bit A/D converters, and Table 2.54 is a comparison of 12-bit A/D converter registers, and Table 2.55 is a comparison of A/D conversion start triggers that can be set in the ADSTRGR registers.

Table 2.53 Comparative Overview of 12-Bit A/D Converters

Item	RX110 (S12ADb)	RX140 (S12ADE)	
Number of units	1 unit	1 unit	
Input channels	14 channels	18 channels	
Extended analog	Temperature sensor output, internal	Temperature sensor output, internal	
function	reference voltage	reference voltage	
A/D conversion method	Successive approximation method	Successive approximation method	
Resolution	12 bits	12 bits	
Conversion time	1.0 µs per channel (when A/D conversion clock ADCLK = 32 MHz)	Per channel Conversion cycle bit = 0: 0.88 µs, conversion cycle bit = 1: 0.67 µs (when A/D conversion clock (ADCLK) = 48 MHz)	
A/D conversion clock	Peripheral module clock PCLK and A/D conversion clock ADCLK can be set so that the frequency ratio should be one of the following. PCLK to ADCLK frequency ratio = 1:1, 1:2, 1:4, 1:8, 2:1, 4:1 ADCLK is set using the clock generation	Peripheral module clock PCLKB and A/D conversion clock ADCLK can be set so that the frequency ratio should be one of the following. PCLKB to ADCLK frequency ratio = 1:1, 1:2, 2:1, 4:1, 8:1 ADCLK is set using the clock generation	
circuit. • 14 registers for analog input and one for A/D-converted data duplication in double trigger mode • One register for temperature sensor output • One register for internal reference • The results of A/D conversion are stored in 12-bit A/D data registers.		 circuit. 18 registers for analog input, one for A/D-converted data duplication in double trigger mode One register for temperature sensor output One register for internal reference One register for self-diagnosis The results of A/D conversion are stored in 12-bit A/D data registers. 12-bit accuracy output for the results of A/D conversion 	

Item	RX110 (S12ADb)	RX140 (S12ADE)
Data registers	In addition mode, A/D conversion results are added and stored in A/D data registers as 14-bit data.	The value obtained by adding up A/D-converted results is stored as a value in the number of bit for conversion accuracy + 2 bits/4 bits in the A/D data registers in A/D-converted value addition mode.
	 Duplication of A/D conversion data — A/D conversion data of one selected analog input channel is stored in A/D data register y when conversion is started by the first trigger and into the duplication register when started by the second trigger. — Duplication is available only in single scan mode or group scan mode when double trigger mode is selected. 	Double trigger mode (selectable in single scan and group scan modes): The first piece of A/D-converted analog-input data on one selected channel is stored in the data register for the channel, and the second piece is stored in the duplication register.
Operating mode	 Single scan mode: A/D conversion is performed only once on the analog inputs of up to 14 channels arbitrarily selected. A/D conversion is performed only once on the temperature sensor output. A/D conversion is performed only once on the internal reference voltage. Continuous scan mode: A/D conversion is performed repeatedly on the analog inputs of up to 14 channels arbitrarily selected. Group scan mode: Analog inputs of up to 14 channels 	 Single scan mode: A/D conversion is performed only once on the analog inputs of up to 18 channels arbitrarily selected. A/D conversion is performed only once on the temperature sensor output. A/D conversion is performed only once on the internal reference voltage. Continuous scan mode: A/D conversion is performed repeatedly on the analog inputs of up to 18 channels arbitrarily selected. Group scan mode: Analog inputs of up to 18 arbitrarily
	are divided into group A and group B, and A/D conversion of the analog inputs selected on a group basis is performed only once. — Conversion start conditions (synchronous trigger) can be selected independently for group A and group B, allowing A/D conversion of the groups to start at different times.	selected channels are divided into group A and group B, and A/D conversion of the analog inputs selected on a group basis is performed only once. — Conversion start conditions (synchronous trigger) can be selected independently for group A and group B, allowing A/D conversion of the groups to start at different times.

Item	RX110 (S12ADb)	RX140 (S12ADE)
Operating mode		 Group scan mode (when group A is given priority): If a group A trigger is input during A/D conversion on group B, A/D conversion on group B is stopped and A/D conversion is performed on group A. Restart (rescan) of A/D conversion on group B after completion of A/D conversion on group A can be enabled.
Conditions for A/D conversion start	 Software trigger Synchronous trigger Trigger by MTU 	 Software trigger Synchronous trigger Trigger by the multi-function timer pulse unit (MTU) or event link controller (ELC)
	 Asynchronous trigger A/D conversion can be triggered by the ADTRG0# pin. 	 Asynchronous trigger A/D conversion can be triggered by the external trigger ADTRG0# pin.
Functions	Variable sampling state count A/D-converted value addition mode	 Variable sampling state count Self-diagnosis of 12-bit A/D converter Selectable A/D-converted value addition mode or average mode Analog input disconnection detection function (discharge function/precharge function)
	Double trigger mode (duplication of A/D conversion data)	 Double trigger mode (duplication of A/D conversion data) Automatic clear function of A/D data registers Compare function (window A and window B) 16 ring buffers when the compare function is used

Item	RX110 (S12ADb)	RX140 (S12ADE)
Interrupt sources	 In the modes except double trigger mode and group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of single scan. In double trigger mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan. In group scan mode, an A/D scan end interrupt request (S12ADI0) can be generated on completion of group A scan, whereas an A/D scan end interrupt request (GBADI) for group B can be generated on completion of group B scan. When double trigger mode is selected in group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan of group A, whereas A/D scan end interrupt request (GBADI) specially for group B can be generated on completion of group B scan. The S12ADI and GBADI interrupts can activate the data transfer controller (DTC). 	 In the modes except double trigger mode and group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of single scan. In double trigger mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan. In group scan mode, an A/D scan end interrupt request (S12ADI0) can be generated on completion of group A scan, whereas an A/D scan end interrupt request (GBADI) for group B can be generated on completion of group B scan. When double trigger mode is selected in group scan mode, A/D scan end interrupt request (S12ADI0) can be generated on completion of double scan of group A, whereas A/D scan end interrupt request (GBADI) specially for group B can be generated on completion of group B scan. The S12ADI0 and GBADI interrupts can activate the data transfer controller (DTC).
Event link function		 An ELC event is generated on completion of scans other than group B scan in group scan mode. An ELC event is generated on completion of group B scan in group scan mode. An ELC event is generated on completion of all scans. Scan can be started by a trigger output by the ELC. An ELC event is generated according to the event conditions of the window compare function in single scan mode.
Low power consumption function	Ability to specify module stop state	Ability to specify module stop state

Table 2.54 Comparison of 12-Bit A/D Converter Registers

Register	Bit	RX110 (S12ADb)	RX140 (S12ADE)
ADDRy	_	A/D data register y	A/D data register y
		(y = 0 to 4, 6, 8 to 15)	(y = 0 to 8, 16 to 21, 24 to 26)
ADRD	—	_	A/D self-diagnosis data register
ADANSA	—	AD channel select register A	_
ADANSA0	—	_	AD channel select register A0
ADANSA1	_	_	AD channel select register A1
ADANSB		AD channel select register B	_
ADANSB0		_	AD channel select register B0
ADANSB1		_	AD channel select register B1
ADADS	_	A/D-converted value addition mode select register	
ADADS0	_	_	A/D-converted value addition/ average channel select register 0
ADADS1	_	_	A/D-converted value addition/ average channel select register 1
ADADC	ADC[1:0] (RX110) ADC[2:0] (RX140)	Addition count select bits (b1, b0) b1 b0	Addition count select bits (b2 to b0) b2 b0
		0 0: 1-time conversion (no addition, same as normal conversion) 0 1: 2-time conversion (1 addition) 1 0: 3-time conversion (2 additions) 1 1: 4-time conversion (3 additions)	0 0 0: 1-time conversion
	AVEE	_	Average mode enable bit
ADCER	DIAGVAL[1:0]	_	Self-diagnosis conversion voltage
	DIAGLE		select bits
	DIAGLD	_	Self-diagnosis mode select bit
ADE://05	DIAGM	-	Self-diagnosis enable bit
ADEXICR	TSS (RX110) TSSA (RX140)	Temperature sensor output A/D conversion select bits	Temperature sensor output A/D conversion select bits
	OCS (RX110) OCSA (RX140)	Internal reference voltage A/D conversion select bits	Internal reference voltage A/D conversion select bits
ADSTRGR	TRSB[3:0] (RX110) TRSB[5:0] (RX140)	A/D conversion start trigger select bits for group B (b0 to b3)	A/D conversion start trigger select bits for group B (b0 to b5)
	TRSA[3:0] (RX110) TRSA[5:0] (RX140)	A/D conversion start trigger select bits (b8 to b11)	A/D conversion start trigger select bits (b8 to b13)
ADSSTRn	_	A/D sampling state register n (n = 0 to 4, 6, L, T, O)	A/D sampling state register n (n = 0 to 8, L, T, O)

Register	Bit	RX110 (S12ADb)	RX140 (S12ADE)
ADDISCR	_		A/D disconnection detection
			control register
ADELCCR		_	A/D event link control register
ADGSPCR		_	A/D group scan priority control register
ADCMPCR	_	_	A/D compare function control register
ADCMPANSR0	_	_	A/D compare function window A channel select register 0
ADCMPANSR1	_	_	A/D compare function window A channel select register 1
ADCMPANSER	_	_	A/D compare function window A extended input select register
ADCMPLR0	_	_	A/D compare function window A comparison condition setting register 0
ADCMPLR1	_	_	A/D compare function window A comparison condition setting register 1
ADCMPLER	_	_	A/D compare function window A extended input comparison condition setting register
ADCMPDR0	_	_	A/D compare function window A lower-side level setting register
ADCMPDR1	_	_	A/D compare function window A upper-side level setting register
ADCMPSR0	_	_	A/D compare function window A channel status register 0
ADCMPSR1	_	_	A/D compare function window A channel status register 1
ADCMPSER	_	_	A/D compare function window A extended input channel status register
ADHVREFCNT	_	_	A/D high-potential/low-potential reference voltage control register
ADWINMON	_	_	A/D compare function window A/B status monitor register
ADCMPBNSR	_	_	A/D compare function window B channel select register
ADWINLLB	_	_	A/D compare function window B lower-side level setting register
ADWINULB	_		A/D compare function window B upper-side level setting register
ADCMPBSR	_	_	A/D compare function window B channel status register
ADBUFn	-	_	A/D data storage buffer register n (n = 0 to 15)
ADBUFEN	_	_	A/D data storage buffer enable register
ADBUFPTR	_		A/D data storage buffer pointer register
ADCCR	_	_	A/D conversion cycle control register

Table 2.55 Comparison of A/D Conversion Start Triggers Set in the ADSTRGR Registers

Bit	RX110 (S12ADb)	RX140 (S12ADE)
TRSB[3:0]	A/D conversion start trigger select for group	A/D conversion start trigger select for group
(RX110)	B bits	B bits
TRSB[5:0]		
(RX140)	b3 b0	b5 b0
		1 1 1 1 1 1: No trigger source selected state
	0 0 0 1: TRG0AN	0 0 0 0 0 1: TRG0AN
	0 0 1 0: TRG0BN	0 0 0 0 1 0: TRG0BN
	0 0 1 1: TRGAN	000011: TRGAN
	0 1 0 0: TRG0EN	0 0 0 1 0 0: TRG0EN
	0 1 0 1: TRG0FN	0 0 0 1 0 1: TRG0FN
		0 0 0 1 1 0: TRG4AN
		0 0 1 1 1 1: TRG4BN
		0 0 1 0 0 0: TRG4ABN
		0 0 1 0 0 1: ELCTRG0
TRSA[3:0] (RX110)	A/D conversion start trigger select bits	A/D conversion start trigger select bits
TRSA[5:0]	b11 b8	b13 b8
(RX140)		1 1 1 1 1 1: No trigger source selected state
	0 0 0 0: ADTRG0#	0 0 0 0 0 0: ADTRG0#
	0 0 0 1: TRG0AN	0 0 0 0 0 1: TRG0AN
	0 0 1 0: TRG0BN	0 0 0 0 1 0: TRG0BN
	0 0 1 1: TRGAN	0 0 0 0 1 1: TRGAN
	0 1 0 0: TRG0EN	0 0 0 1 0 0: TRG0EN
	0 1 0 1: TRG0FN	0 0 0 1 0 1: TRG0FN
		0 0 0 1 1 0: TRG4AN
		0 0 0 1 1 1: TRG4BN
		0 0 1 0 0 0: TRG4ABN
		0 0 1 0 0 1: ELCTRG0

2.22 Temperature Sensor

Table 2.56 is a comparison of temperature sensor registers.

Table 2.56 Comparison of Temperature Sensor Registers

Register	Bit	RX110 (TEMPSA)	RX140 (TEMPSA)
TSCDRH,	_	Temperature sensor calibration	Temperature sensor calibration
TSCDRL (RX110)		data register	data register
TSCDR (RX140)			

2.23 Data Operation Circuit

Table 2.57 is a comparative overview of data operation circuit.

Table 2.57 Comparative Overview of Data Operation Circuit

Item	RX110	RX140	
Data operation function	16-bit data comparison, addition, and	16-bit data comparison, addition, and	
	subtraction	subtraction	
Low power consumption function	Ability to specify module stop state	Ability to specify module stop state	
Interrupts	The compared values either match or mismatch	The compared values either match or mismatch	
	The result of data addition is greater than FFFFh	The result of data addition is greater than FFFFh (overflow)	
	The result of data subtraction is less than 0000h	The result of data subtraction is less than 0000h (underflow)	
Event linking function (output)	_	The compared values either match or mismatch	
		The result of data addition is greater than FFFFh (overflow)	
		The result of data subtraction is less than 0000h (underflow)	

2.24 RAM

Table 2.58 is a comparative overview of RAM.

Table 2.58 Comparative Overview of RAM

Item	RX110	RX140
RAM capacity	Max. 16 KB	Max. 64 KB
RAM address	 RAM capacity 16 KB RAM0: 0000 0000h to 0000 3FFFh RAM capacity 10 KB RAM0: 0000 0000h to 0000 27FFh RAM capacity 8 KB RAM0: 0000 0000h to 0000 1FFFh 	 RAM capacity 64 KB RAM0: 0000 0000h to 0000 FFFFh RAM capacity 32 KB RAM0: 0000 0000h to 0000 7FFFh RAM capacity 16 KB RAM0: 0000 0000h to 0000 3FFFh
Low power consumption function	 Single-cycle access is possible for both reading and writing. RAM can be enabled or disabled. Ability to specify module stop state 	 Single-cycle access is possible for both reading and writing. RAM can be enabled or disabled. Ability to specify module stop state

2.25 Flash Memory

Table 2.59 is a comparative overview of flash memory, and Table 2.60 is a comparison of flash memory registers.

Table 2.59 Comparative Overview of Flash Memory

Item	RX110	RX140 (FLASH)	
Memory capacity	 User area: Up to 128 KB Extra area: Stores the start-up area information, access window information, and unique ID 	 User area: Up to 256 KB Data area: Up to 8 KB Extra area: Stores the start-up area information, access window information, and unique ID 	
Addresses Software commands	 Products with capacity of 128 KB FFFE 0000h to FFFF FFFFh Products with capacity of 96 KB FFFE 8000h to FFFF FFFFh Products with capacity of 64 KB FFFF 0000h to FFFF FFFFh Products with capacity of 32 KB FFFF 8000h to FFFF FFFFh The following software commands are implemented: 	 Products with capacity of 256 KB FFFC 0000h to FFFF FFFFh Products with capacity of 128 KB FFFE 0000h to FFFF FFFFh Products with capacity of 64 KB FFFF 0000h to FFFF FFFFh The following software commands are implemented: 	
	Program, blank check, block erase, and unique ID read The following commands are implemented for programming the extra area: Start-up area information program and access window information program	Program, blank check, block erase, and all-block erase The following commands are implemented for programming the extra area: Start-up area information program, access window protect, and access window information program	
Value after erasure	ROM: FFh	ROM: FFh E2 DataFlash: FFh	
Interrupt	An interrupt (FRDYI) is generated upon completion of software command processing or forced stop processing.	An interrupt (FRDYI) is generated upon completion of software command processing or forced stop processing.	
On-board programming	 Boot mode (SCI interface) Channel 1 of the serial communications interface (SCI1) is used for asynchronous communication. The user area can be programmed. Boot mode (FINE interface) The FINE interface is used. The user area can be programmed. Self-programming (single-chip mode) The user area can be programmed using a flash programming routine in a user program. 	Boot mode (SCI interface) Channel 1 of the serial communications interface (SCI1) is used for asynchronous communication. The user area and data area can be programmed. Boot mode (FINE interface) The FINE interface is used. The user area and data area can be programmed. Self-programming (single-chip mode) The user area and data area can be programmed using a flash programming routine in a user program.	

Item	RX110	RX140 (FLASH)
Off-board programming	The user area can be programmed using a flash programmer compatible with the MCU.	The user area and data area can be programmed using a flash programmer compatible with the MCU.
ID code protection	 Connection with a serial programmer can be controlled using ID codes in boot mode. Connection with an on-chip debugging emulator can be controlled using ID codes. 	 Connection with a serial programmer can be controlled using ID codes in boot mode. Connection with an on-chip debugging emulator can be controlled using ID codes.
Start-up program protection function	This function is used to safely program blocks 0 to 15.	This function is used to safely program blocks 0 to 7.
Area protection	During self-programming, this function enables programming only of specified blocks in the user area and disables programming of the other blocks.	During self-programming, this function enables programming only of specified blocks in the user area and disables programming of the other blocks.
Background operation (BGO) function	_	Programs in the ROM can run while the E2 DataFlash is being programmed.

Table 2.60 Comparison of Flash Memory Registers

Register	Bit	RX110	RX140 (FLASH)
DFLCTL	_	_	E2 DataFlash control register
FENTRYR	FENTRYD	_	E2 DataFlash P/E mode entry bit
MEMWAITR	_	_	Memory wait cycle setting register
DFLWAITR	_	_	Data flash wait cycle setting register
FPMCR	FMS0, FMS1, FSM2 (RX110) FMS0, FMS1 (RX140)	Flash operating mode select bits 0, 1, and 2 FMS2 FMS1 FMS0	Flash operating mode select bits 0 and 1 FMS1 FMS0
	(177140)	0 0 0: ROM read mode	0 0: ROM/E2 DataFlash read mode 0 1: ROMP/E mode 1 0: E2 DataFlash P/E mode
		0 1 1: Discharge mode 1 1 0 1: ROM P/E mode 1 1 1: Discharge mode 2 Settings other than the above are prohibited.	1 1: Setting prohibited
	LVPE	Low-voltage P/E mode enable bit	_
FISR	PCKA[4:0] (RX110) PCKA[5:0] (RX140)	Peripheral clock notification bits	Peripheral clock notification bits
FASR	EXS	Extra area select bit	Extra area select bit
		0: User area	0: User area or data area
		1: Extra area	1: Extra area

Register	Bit	RX110	RX140 (FLASH)
FCR	CMD[3:0]	Software command setting bits	Software command setting bits
		b3 b0	b3 b0
		0 0 0 1: Program	0 0 0 1: Program
		0 0 1 1: Blank check	0 0 1 1: Blank check
		0 1 0 0: Block erase	0 1 0 0: Block erase
		0 1 0 1: Unique ID read	
			0 1 1 0: All-block erase
		Settings other than the above are	Settings other than the above are
		prohibited.	prohibited.
	DRC	Data read completion bit	_
FEXCR	CMD[2:0]	Software command setting bits	Software command setting bits
		b2 b0	b2 b0
		0 0 1: Start-up area information	0 0 1: Start-up area information
		program	program/access window
			protect
		0 1 0: Access window information	0 1 0: Access window information
		program	program
		Settings other than the above are prohibited.	Settings other than the above are prohibited.
FSARH		Flash processing start address	Flash processing start address
I SAKII		register H	register H
		l register i	register i
		FSARH is an 8-bit register.	FSARH is a 16-bit register.
FEARH		Flash processing end address	Flash processing end address
		register H	register H
		FEARH is an 8-bit register.	FEARH is a 16-bit register.
FRBH	_	Flash read buffer register H	_
FRBL	_	Flash read buffer register L	_
FWBH, FWBL	_	Flash write buffer register H,	Flash write buffer register n
(RX110)		Flash write buffer register L	(n = 0 to 3)
FWBn (RX140)			
FSTATR1	DRRDY	Data read ready flag	-
FEAMH	_	Flash error address monitor	Flash error address monitor
		register H	register H
		FEAMH is an 8-bit register.	FEAMH is a 16-bit register.
FSCMR	AWPR	_	Access window protect flag
FAWSMR	_	Flash access window start address	Flash access window start address
		monitor register	monitor register
		Initial value after a reset differs.	
FAWEMR	_	Flash access window end address	Flash access window end address
		monitor register	monitor register
		Initial value after a reset differs.	
UIDRn	_	Unique ID register n (n = 0 to 31)	Unique ID register n (n = 0 to 3)
		UIDRn is an 8-bit register.	UIDRn is a 32-bit register.

2.26 Packages

As indicated in Table 2.61, there are discrepancies in the package drawing codes and availability of some package types, and this should be borne in mind at the board design stage. For details, refer to Design Guide for Migration between RX Family: Differences in Package External form (R01AN4591EJ).

Table 2.61 Packages

	Renesas Code		
Package Type	RX110	RX140	
80-pin LFQFP	×	0	
64-pin LFQFP	×	0	
64-pin WFLGA	0	×	
48-pin LFQFP	PLQP0048KB-A	PLQP0048KB-B	
48-pin HWQFN	PWQN0048KB-A	PWQN0048KC-A	
40-pin HWQFN	0	×	
36-pin WFLGA	0	X	
32-pin LQFP	×	0	
32-pin HWQFN	×	0	

^{○:} Package available (Renesas code omitted); X: Package not available

3. Comparison of Pin Functions

This section presents a comparative description of pin functions as well as a comparison of the pins for the power supply, clocks, and system control. Items that exist only on one group are indicated by **blue text**. Items that exists on both groups with different specifications are indicated by **red text**. **Black text** indicates there is no differences in the item's specifications between groups.

3.1 64-Pin Package

Table 3.1 is a comparative listing of the pin functions of 64-pin package products.

Table 3.1 Comparative Listing of 64-Pin Package Pin Functions

64-Pin LFQFP/		
LQFP	RX110	RX140
1	P03	P03*1/DA0
2	P27/MTIOC2B/SCK1/SCK12/IRQ3/CMPA2/ CACREF/ADTRG0#	VCL
3	P26/MTIOC2A/TXD1/SMOSI1/SSDA1	MD/PG7/FINED
4	P30/RXD1/SMISO1/SSCL1/IRQ0	XCIN/PH7*3
5	P31/CTS1#/RTS1#/SS1#/IRQ1	XCOUT/PH6*3
6	MD/FINED	RES#
7	RES#	XTAL/P37/IRQ4
8	XCOUT	VSS
9	XCIN	EXTAL/P36/IRQ2
10	P35/NMI	VCC
11	XTAL	P35/NMI
12	EXTAL	P32/MTIOC0C/TMO3/TXD6*3/SMOSI6*3/ SSDA6*3/TS0*3/IRQ2/RTCOUT
13	VCL	P31/MTIOC4D/TMCI2/CTS1#/RTS1#/SS1#/ TS1*3/IRQ1
14	VSS	P30/MTIOC4B/TMRI3/POE8#/RXD1/ SMISO1/SSCL1/TS2*3/IRQ0
15	VCC	P27/MTIOC2B/TMCI3/SCK1/TS3
16	P32/MTIOC0C/RTCOUT/IRQ2	P26/MTIOC2A/TMO1/LPTO/TXD1/SMOSI1/ SSDA1/TS4
17	P17/MTIOC0C/SCK1/MISOA/SDA0/RXD12/ RXDX12/SMISO12/SSCL12/IRQ7	P17/MTIOC3A/MTIOC3B/TMO1/POE8#/ SCK1/MISOA/SDA0/IRQ7
18	P16/RTCOUT/TXD1/SMOSI1/SSDA1/ MOSIA/SCL0/IRQ6/ADTRG0#	P16/MTIOC3C/MTIOC3D/TMO2/TXD1/ SMOSI1/SSDA1/MOSIA/SCL0/IRQ6/ RTCOUT/ADTRG0#
19	P15/MTIOC0B/MTCLKB/RXD1/SMISO1/ SSCL1/RSPCKA/IRQ5/CLKOUT	P15/MTIOC0B/MTCLKB/TMCI2/RXD1/ SMISO1/SSCL1/CRXD0/TS5*3/IRQ5
20	P14/MTIOC0A/MTCLKA/CTS1#/RTS1#/ SS1#/SSLA0/TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12/IRQ4	P14/MTIOC3A/MTCLKA/TMRI2/CTS1#/ RTS1#/SS1#/CTXD0/TS6*3/IRQ4
21	PH3/MTIOC1A	PH3/MTIOC4D/TMCI0/TS7*3
22	PH2/IRQ1	PH2/MTIOC4C/TMRI0/TS8*3/IRQ1
23	PH1/IRQ0	PH1/MTIOC3D/TMO0/TS9*3/IRQ0
24	PH0/MTIOC1B/CACREF	PH0/MTIOC3B/TS10*3/CACREF
25	P55	P55/MTIOC4A/MTIOC4D/TMO3/CRXD0/ TS11*3
26	P54	P54/MTIOC4B/TMCI1/CTXD0/TS12*3

64-Pin LFQFP/		
LPQFP	RX110	RX140
27	PC7/MTCLKB/TXD1/SMOSI1/SSDA1/ MISOA/CACREF	PC7/MTIOC3A/MTCLKB/TMO2/LPTO/ TXD8*3/SMOSI8*3/SSDA8*3/MISOA/TS13/ CACREF
28	PC6/MTCLKA/RXD1/SMISO1/SSCL1/ MOSIA	PC6/MTIOC3C/MTCLKA/TMCI2/RXD8*3/ SMISO8*3/SSCL8*3/MOSIA/TS14
29	PC5/MTCLKD/SCK1/RSPCKA	PC5/MTIOC0C/MTIOC3B/MTCLKD/TMRI2/ SCK8*3/RSPCKA/TS15
30	PC4/MTCLKC/SCK5/SSLA0/IRQ2/CLKOUT	PC4/MTIOC0A/MTIOC3D/MTCLKC/TMCI1/ POE0#/SCK5/CTS8#*3/RTS8#*3/SS8#*3/ SSLA0/TSCAP
31	PC3/TXD5/SMOSI5/SSDA5	PC3/MTIOC4D/TXD5/SMOSI5/SSDA5/ TS16*3
32	PC2/RXD5/SMISO5/SSCL5/SSLA3	PC2/MTIOC4B/RXD5/SMISO5/SSCL5/ SSLA3/TS17*3
33	PB7/PC1	PB7/PC1*2/MTIOC3B/TXD9*3/SMOSI9*3/ SSDA9*3/TS18*3
34	PB6/PC0	PB6/PC0*2/MTIOC3D/RXD9*3/SMISO9*3/ SSCL9*3/TS19*3
35	PB5/MTIOC2A/MTIOC1B	PB5/MTIOC2A/MTIOC1B/TMRI1/POE1#/ SCK9*3/TS20*3
36	PB3/MTIOC0A	PB3/MTIOC0A/MTIOC4A/TMO0/POE3#/ LPTO/SCK6*3/TS22*3
37	PB1/MTIOC0C/IRQ4	PB1/MTIOC0C/MTIOC4C/TMCI0/TXD6*3/ SMOSI6*3/SSDA6*3/TS24*3/IRQ4/CMPOB1
38	VCC	VCC
39	PB0/MTIC5W/MTIOC0C/RTCOUT/SCL0/ RSPCKA/IRQ2/ADTRG0#	PB0/MTIOC3D/MTIC5W/RXD6*3/SMISO6*3/ SSCL6*3/RSPCKA/TS25
40	VSS	VSS
41	PA6/MTIC5V/MTCLKB/MTIOC2A/CTS5#/ RTS5#/SS5#/SDA0/MOSIA/IRQ3	PA6/MTIOC3D/MTIC5V/MTCLKB/TMCI3/ POE2#/CTS5#/RTS5#/SS5#/MOSIA/TS26*3
42	PA4/MTIC5U/MTCLKA/MTIOC2B/TXD5/ SMOSI5/SSDA5/SSLA0/IRQ5	PA4/MTIOC4C/MTIC5U/MTCLKA/TMRIO/ TXD5/SMOSI5/SSDA5/SSLA0/TS28/IRQ5/ CVREFB1
43	PA3/MTIOC0D/MTCLKD/MTIOC1B/RXD5/ SMISO5/SSCL5/MISOA/IRQ6	PA3/MTIOC0D/MTIOC4D/MTIC5V/MTCLKD/ RXD5/SMISO5/SSCL5/TS29/IRQ6/CMPB1
44	PA1/MTIOC0B/MTCLKC/RTCOUT/SCK5/ SSLA2	PA1/MTIOC0B/MTIOC3B/MTCLKC/SCK5/ SSLA2/TS31
45	PA0/SSLA1/CACREF	PA0/MTIOC4A/SSLA1/TS32*3/CACREF
46	PE5/MTIOC2B/IRQ5/AN013	PE5/MTIOC4C/MTIOC2B/IRQ5/AN021/ CMPOB0
47	PE4/MTIOC1A/MOSIA/IRQ4/AN012	PE4/MTIOC4D/MTIOC1A/MTIOC4A/TS33/ AN020/CMPA2/CLKOUT
48	PE3/MTIOC0A/MTIOC1B/CTS12#/RTS12#/ SS12#/RSPCKA/IRQ3/AN011	PE3/MTIOC1B/MTIOC4B/POE8#/CTS12#/ RTS12#/SS12#/TS34/AN019/CLKOUT
49	PE2/RXD12/RXDX12/SMISO12/SSCL12/ IRQ7/AN010	PE2/MTIOC4A/RXD12/RXDX12/SMISO12/ SSCL12/TS35/IRQ7/AN018/CVREFB0
50	PE1/TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12/IRQ1/AN009	PE1/MTIOC4C/TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12/AN017/CMPB0
51	PE0/MTIOC2A/SCK12/IRQ0/AN008	PE0/SCK12/AN016
52	PE7/IRQ7/AN015	P47*1/AN007
53	PE6/IRQ6/AN014	P46*1/AN006

64-Pin LFQFP/ LQFP	RX110	RX140	
54	P46*1/AN006	P45*1/AN005	
55	P44*1/AN004	P44*1/AN004	
56	P43*1/AN003	P43*1/AN003	
57	P42*1/AN002	P42*1/AN002	
58	P41*1/AN001	P41*1/AN001	
59	VREFL0/PJ7*1	VREFL0/PJ7*1	
60	P40*1/AN000	P40*1/AN000	
61	VREFH0/PJ6*1	VREFH0/PJ6*1	
62	AVSS0	AVCC0	
63	AVCC0	P05*1/DA1	
64	P05	AVSS0	

Notes: 1. The power supply of the I/O buffer for these pins is AVCCO.

- 2. PC0 and PC1 are valid only when the port switching function is selected.
- 3. Not implemented on products with ROM capacity of 64 KB.

3.2 48-Pin Package

Table 3.2 is a comparative listing of the pin functions of 48-pin package products.

Table 3.2 Comparative Listing of 48-Pin Package Pin Functions

48-Pin LFQFP/			
HWQFN	RX110	RX140	
1	P27/MTIOC2B/SCK1/SCK12/IRQ3/CMPA2/ CACREF/ADTRG0#	VCL	
2	P26/MTIOC2A/TXD1/SMOSI1/SSDA1	MD/PG7/FINED	
3	MD/FINED	RES#	
4	RES#	XTAL/P37/IRQ4	
5	XCOUT	VSS	
6	XCIN	EXTAL/P36/IRQ2	
7	P35/NMI	VCC	
8	XTAL	P35/NMI	
9	EXTAL	P31/MTIOC4D/TMCI2/CTS1#/RTS1#/SS1#/ TS1*3/IRQ1	
10	VCL	P30/MTIOC4B/TMRI3/POE8#/RXD1/ SMISO1/SSCL1/TS2*3/IRQ0	
11	VSS	P27/MTIOC2B/TMCI3/SCK1/TS3	
12	VCC	P26/MTIOC2A/TMO1/LPTO/TXD1/SMOSI1/ SSDA1/TS4	
13	P17/MTIOCOC/SCK1/MISOA/SDA0/RXD12/ RXDX12/SMISO12/SSCL12/IRQ7	P17/MTIOC3A/MTIOC3B/TMO1/POE8#/ SCK1/MISOA/SDA0/IRQ7	
14	P16/RTCOUT/TXD1/SMOSI1/SSDA1/ MOSIA/SCL0/IRQ6/ADTRG0#	P16/MTIOC3C/MTIOC3D/TMO2/TXD1/ SMOSI1/SSDA1/MOSIA/SCL0/IRQ6/ ADTRG0#/RTCOUT	
15	P15/MTIOC0B/MTCLKB/RXD1/SMISO1/ SSCL1/RSPCKA/IRQ5/CLKOUT	P15/MTIOC0B/MTCLKB/TMCI2/RXD1/ SMISO1/SSCL1/CRXD0/TS5*3/IRQ5	
16	P14/MTIOC0A/MTCLKA/CTS1#/RTS1#/ SS1#/SSLA0/TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12/IRQ4	P14/MTIOC3A/MTCLKA/TMRI2/CTS1#/ RTS1#/SS1#/CTXD0/TS6*3/IRQ4	
17	PH3/MTIOC1A	PH3/MTIOC4D/TMCI0/TS7*3	
18	PH2/IRQ1	PH2/MTIOC4C/TMRI0/TS8*3/IRQ1	
19	PH1/IRQ0	PH1/MTIOC3D/TMO0/TS9*3/IRQ0	
20	PH0/MTIOC1B/CACREF	PH0/MTIOC3B/TS10*3/CACREF	
21	PC7/MTCLKB/TXD1/SMOSI1/SSDA1/ MISOA/CACREF	PC7/MTIOC3A/TMO2/MTCLKB/LPTO/ TXD8*3/SMOSI8*3/SSDA8*3/MISOA/TS13/ CACREF	
22	PC6/MTCLKA/RXD1/SMISO1/SSCL1/MOSIA	PC6/MTIOC3C/MTCLKA/TMCI2/RXD8*3/ SMISO8*3/SSCL8*3/MOSIA/TS14	
23	PC5/MTCLKD/SCK1/RSPCKA	PC5/MTIOC0C/MTIOC3B/MTCLKD/TMRI2/ SCK8*3/RSPCKA/TS15	
24	PC4/MTCLKC/SCK5/SSLA0/IRQ2/CLKOUT	PC4/MTIOC0A/MTIOC3D/MTCLKC/TMCI1/ POE0#/SCK5/CTS8#*3/RTS8#*3/SS8#*3/ SSLA0/TSCAP	
25	PB5/PC3/MTIOC2A/MTIOC1B	PB5/PC3*1/MTIOC2A/MTIOC1B/TMRI1/ POE1#/TS20*3	
26	PB3/PC2/MTIOC0A	PB3/PC2*1/MTIOC0A/MTIOC4A/TMO0/ POE3#/LPTO/SCK6*3/TS22*3	

48-Pin		
LFQFP/		
HWQFN	RX110	RX140
27	PB1/PC1/MTIOC0C/IRQ4	PB1/PC1*1/MTIOC0C/MTIOC4C/TMCI0/
		TXD6*3/SMOSI6*3/SSDA6*3/TS24*3/IRQ4/
		CMPOB1
28	VCC	VCC
29	PB0/PC0/MTIC5W/MTIOC0C/RTCOUT/	PB0/PC0*1/MTIOC3D/MTIC5W/RXD6*3/
	SCL0/RSPCKA/IRQ2/ADTRG0#	SMISO6*3/SSCL6*3/RSPCKA/TS25
30	VSS	VSS
31	PA6/MTIC5V/MTCLKB/MTIOC2A/CTS5#/	PA6/MTIOC3D/MTIC5V/MTCLKB/TMCI3/
	RTS5#/SS5#/SDA0/MOSIA/IRQ3	POE2#/CTS5#/RTS5#/SS5#/MOSIA/TS26*3
32	PA4/MTIC5U/MTCLKA/MTIOC2B/TXD5/	PA4/MTIOC4C/MTIC5U/MTCLKA/TMRIO/
	SMOSI5/SSDA5/SSLA0/IRQ5	TXD5/SMOSI5/SSDA5/SSLA0/TS28/IRQ5/
		CVREFB1
33	PA3/MTIOC0D/MTCLKD/MTIOC1B/RXD5/	PA3/MTIOC0D/MTIOC4D/MTIC5V/MTCLKD/
0.4	SMISO5/SSCL5/MISOA/IRQ6	RXD5/SMISO5/SSCL5/TS29/IRQ6/CMPB1
34	PA1/MTIOC0B/MTCLKC/RTCOUT/SCK5/ SSLA2	PA1/MTIOC0B/MTIOC3B/MTCLKC/SCK5/
0.5	PE4/MTIOC1A/MOSIA/IRQ4/AN012	SSLA2/TS31 PE4/MTIOC4D/MTIOC1A/MTIOC4A/TS33/
35	PE4/WITIOCTA/MOSIA/IRQ4/ANUTZ	AN020/CMPA2/CLKOUT
36	PE3/MTIOC0A/MTIOC1B/CTS12#/RTS12#/	PE3/MTIOC1B/MTIOC4B/POE8#/CTS12#/
	SS12#/RSPCKA/IRQ3/AN011	RTS12#/TS34/AN019/CLKOUT
37	PE2/RXD12/RXDX12/SMISO12/SSCL12/	PE2/MTIOC4A/RXD12/RXDX12/SSCL12/
	IRQ7/AN010	TS35/IRQ7/AN018/CVREFB0
38	PE1/TXD12/TXDX12/SIOX12/SMOSI12/	PE1/MTIOC4C/TXD12/TXDX12/SIOX12/
	SSDA12/IRQ1/AN009	SSDA12/AN017/CMPB0
39	PE0/MTIOC2A/SCK12/IRQ0/AN008	P47*2/AN007
40	PE7/IRQ7/AN015	P46*2/AN006
41	P46*2/AN006	P45*2/AN005
42	P42*2/AN002	P42*2/AN002
43	P41*2/AN001	P41*2/AN001
44	VREFL0/PJ7*2	VREFL0/PJ7*2
45	P40*2/AN000	P40*2/AN000
46	VREFH0/PJ6*2	VREFH0/PJ6*2
47	AVSS0	AVCC0
48	AVCC0	AVSS0
L	1	1

Notes: 1. PC0 to PC3 are valid only when the port switching function is selected.

- 2. The power supply of the I/O buffer for these pins is AVCCO.
- 3. Not implemented on products with ROM capacity of 64 KB.

4. Important Information when Migrating Between MCUs

This section presents important information on differences between the RX140 Group and the RX110 Group. 4.1, Notes on Functional Design, presents information regarding the software.

4.1 Notes on Functional Design

Some software that runs on the RX110 Group is compatible with the RX140 Group. Nevertheless, appropriate caution must be exercised due to differences in aspects such as operation timing and electrical characteristics.

Software-related considerations regarding function settings that differ between the RX140 Group and RX110 Group are as follows:

For differences between modules and functions, refer to 2, Comparative Overview of Specifications. For further information, refer to the User's Manual: Hardware of each MCU group, listed in 5, Reference Documents.

4.1.1 12-Bit AD Converter

The RX140 Group incorporates significant changes to the 12-bit A/D converter registers, compared to the RX110 Group. This results in a reduction in software compatibility.

4.1.2 Exception Vector Table

On the RX110 Group the vector table is assigned to a fixed address space, but on the RX140 Group the vector table address can be changed by specifying a value for the start address in the exception table register (EXTB).

4.1.3 Restrictions on Comparison Function

On the RX140 Group the comparison function of the 12-bit A/D converter has the following restrictions:

- Use of the self-diagnostic function and double-trigger mode are prohibited.
 (The ADRD and ADDBLDR registers are not covered by the comparison function.)
- 2. Single scan mode must be used for matching or unmatching event output.
- 3. When temperature sensor or internal reference voltage is selected for window A, operation of window B is prohibited.
- 4. When temperature sensor or internal reference voltage is selected for window B, operation of window A is prohibited.
- 5. The same channel cannot be set for both window A and window B.
- 6. Single scan mode must be selected in order to use the buffer function. (The buffer function cannot be used in conjunction with double trigger mode.)
- 7. It is necessary to make settings such that high-side reference value ≥ low-side reference value.

4.1.4 Port Direction Register (PDR) Initialization

PDR register initialization differs even between products with the same pin count.



4.1.5 Scan Conversion Time of 12-Bit A/D Converter

The scan conversion time of the 12-bit A/D converter differs on the RX110 Group and RX140 Group. The scan conversion time (t_{SCAN}) for single scan operation where the number of selected channels is n is shown below for each group. For details, refer to the description of analog input sampling and scan conversion time on the 12-bit A/D converter in the User's Manual: Hardware of the RX110 Group and RX140 Group, respectively, listed in 5, Reference Documents.

RX110: $t_{SCAN} = t_D + (t_{SPL} + t_{CONV}) n + t_{ED}$

RX140: $t_{SCAN} = t_D + (t_{DIS} \times n) + t_{DIAG} + (t_{CONV} \times n) + t_{ED}$

t_D: Start-of-scanning-delay time

tspl: Sampling time

tois: Disconnection detection assistance processing time

t_{DIAG}: Self-diagnosis A/D conversion processing time

tconv: A/D conversion processing time

ted: End-of-scanning-delay time

4.1.6 I²C Bus Interface Noise Cancellation

The RX110 Group incorporates analog noise filters for the SCL and SDA lines, but the RX140 Group does not have analog noise filters.

5. Reference Documents

User's Manual: Hardware

RX110 Group User's Manual: Hardware Rev.1.20 (R01UH0421EJ0120)

(The latest version can be downloaded from the Renesas Electronics website.)

RX140 Group User's Manual: Hardware Rev.1.10 (R01UH0905EJ0110)

(The latest version can be downloaded from the Renesas Electronics website.)

Application Note

RX Family Design Guide for Migration between RX Family Differences in Package External Form (R01AN4591EJ)

(The latest version can be downloaded from the Renesas Electronics website.)

Technical Updates/Technical News

(The latest information can be downloaded from the Renesas Electronics website.)



Related Technical Updates

This application note reflects the content of the following technical updates:

TN-RX*-A180A/E

TN-RX*-A193A/E

TN-RX*-A194A/E

TN-RX*-A0230A/E

TN-RX*-A0224B/E

TN-RX*-A0241B/E

TN-RX*-A0258A/E



Revision History

		Description	
Rev.	Date	Page	Summary
1.00	Jun. 24, 2021	_	First edition issued
1.10	Mar.28, 2022	16	Revised: Table 2.9 Comparison of Clock Generation Circuit Registers
		29	Revised: Table 2.24 Comparative Overview of I/O Ports (64-Pin)
		82	Revised: Table 3.1 Comparative Listing of 64-Pin Package Pin Functions
1.11	May.26, 2022	82	Revised: Table 3.1 Comparative Listing of 64-Pin Package Pin Functions
		85	Revised: Table 3.2 Comparative Listing of 48-Pin Package Pin Functions

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

- 6. Voltage application waveform at input pin
 - Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).
- 7. Prohibition of access to reserved addresses
 - Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.
- 8. Differences between products
 - Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan www.renesas.com

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